

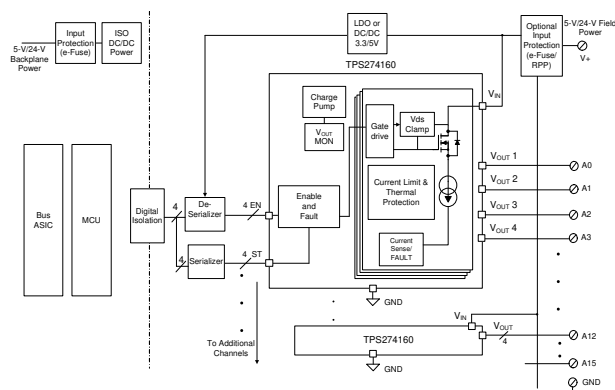
# TPS274160x 160mΩ クワッドチャンネル・スマート・ハイサイド・スイッチ

## 1 特長

- クワッドチャンネル 160mΩ のスマート・ハイサイド・スイッチ
- 広い DC 動作電圧範囲: 5V~36V
  - 絶対最大定格電圧 50V
- 高精度の可変電流制限 (250mA~4A)
- インテリジェントな診断機能
  - TPS274160A: オープン・ドレインの障害出力
  - TPS274160B: アナログ電流センス
  - オフ状態での開放負荷または電源への短絡の検出
- 堅牢な保護機能
  - 短絡保護
  - 誘導性負荷のフライバック・クランプ
  - 低電圧誤動作防止 (UVLO) 保護
  - GND 喪失保護
- VS および OUT ピンの非常に優れた ESD 保護
  - ±8/±15kV IEC 61000-4-2 ESD 接触/気中放電
- 小型の 28 ピン・リードレス QFN パッケージで供給
- 機能安全対応
  - 機能安全システムの設計に役立つ資料を利用可能

## 2 アプリケーション

- デジタル出力モジュール
- スタンドアロンのリモート I/O
- モータ・ドライブ
- ソレノイドまたはバルブ・ドライブ



アプリケーションの例

## 3 概要

TPS274160 デバイスは、4 つの 160mΩ NMOS パワー FET とそれらのゲートを駆動するためのチャージポンプを内蔵したスマート・ハイサイド・スイッチです。本デバイスは、ワット数の低い電球、LED、リレー、ソレノイド、ヒーターなどの各種負荷 (誘導性、容量性、抵抗性) とサブモジュールを駆動するための堅牢な保護および診断機能を備えています。本デバイスは、マルチチャンネルから複数チャンネルの並列接続まで柔軟に出力を構成でき、またスペースに制約のあるアプリケーションで使用できるように超小型の WQFN パッケージに封止されています。

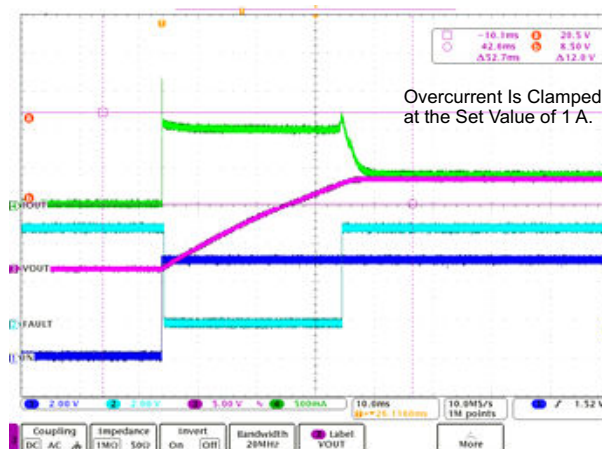
本デバイスは短絡イベントと過熱イベントに対して保護されており、フォルト・イベント中、出力を安全に遮断します。本デバイスは外部可変電流制限機能も備えています。この機能により、大きな容量性負荷を駆動する際の突入電流を低減させ、過負荷電流を最小限に抑えることでシステム電源がブラウン・アウト状態になるのを防止できるため、システムの信頼性を向上させることができます。

モジュールのインテリジェント性能を向上させ予知保全機能を実現するため、本デバイスは出力電流監視 (バージョン B)、開放負荷検出などの診断機能も内蔵しています。

### 製品情報

部品番号	パッケージ <sup>(1)</sup>	本体サイズ
TPS274160A	WQFN (28)	4mm × 5mm
TPS274160B		

- (1) 利用可能なすべてのパッケージについては、このデータシートの末尾にある注文情報を参照してください。



可変電流制限による容量性負荷の駆動



## Table of Contents

<b>1 特長</b> .....	1	8.4 Device Functional Modes.....	26
<b>2 アプリケーション</b> .....	1	<b>9 Application and Implementation</b> .....	27
<b>3 概要</b> .....	1	9.1 Application Information.....	27
<b>4 Revision History</b> .....	2	9.2 Typical Application.....	28
<b>5 Device Comparison Table</b> .....	3	9.3 Capacitive Load Drive and Application Curves.....	28
<b>6 Pin Configuration and Functions</b> .....	4	<b>10 Power Supply Recommendations</b> .....	29
<b>7 Specifications</b> .....	5	<b>11 Layout</b> .....	30
7.1 Absolute Maximum Ratings .....	5	11.1 Layout Guidelines.....	30
7.2 ESD Ratings .....	5	11.2 Layout Examples.....	30
7.3 Recommended Operating Conditions .....	6	<b>12 Device and Documentation Support</b> .....	31
7.4 Thermal Information .....	6	12.1 ドキュメントの更新通知を受け取る方法.....	31
7.5 Electrical Characteristics .....	6	12.2 サポート・リソース.....	31
7.6 Switching Characteristics .....	8	12.3 Trademarks.....	31
7.7 Typical Characteristics.....	10	12.4 静電気放電に関する注意事項.....	31
<b>8 Detailed Description</b> .....	13	12.5 用語集.....	31
8.1 Overview.....	13	<b>13 Mechanical, Packaging, and Orderable Information</b> .....	31
8.2 Functional Block Diagram.....	14		
8.3 Feature Description.....	14		

## 4 Revision History

### Changes from Revision \* (May 2020) to Revision A (November 2020)

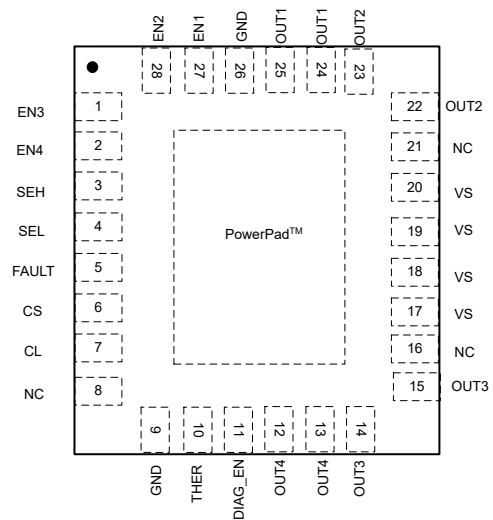
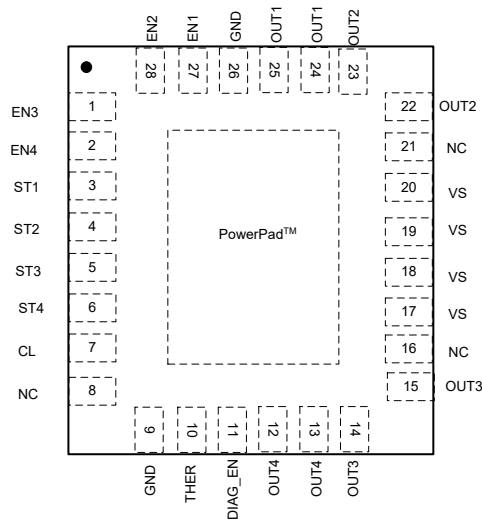
Page

- |  |   |
|--|---|
| • 文書全体にわたって表、図、相互参照の採番方法を更新.....       | 1 |
| • データシートのステータスを「事前情報」から「量産データ」に変更..... | 1 |

## 5 Device Comparison Table

PART NO.	FAULT REPORTING MODE
TPS274160A	Open-drain digital output
TPS274160B	Current-sense analog output

## 6 Pin Configuration and Functions



NC – No internal connection

NC – No internal connection

**图 6-1. RLH Package 28-Pin WQFN With Exposed Thermal Pad TPS274160A Top View**

**图 6-2. RLH Package 28-Pin WQFN With Exposed Thermal Pad TPS274160B Top View**

**表 6-1. Pin Functions**

NAME	PIN		I/O	DESCRIPTION
	TPS274160			
	Version A	Version B		
CL	7	7	O	Adjustable current limit. Connect to device GND if external current limit is not used.
CS	—	6	O	Current-sense output.
DIAG_EN	11	11	I	Enable-disable pin for diagnostics; internal pulldown.
FAULT	—	5	O	Global fault report with open-drain structure, ORed logic for quad-channel fault conditions.
GND	9,26	9, 26	—	Ground pin.
EN1	27	27	I	Input control for channel 1 activation; internal pulldown.
EN2	28	28	I	Input control for channel 2 activation; internal pulldown.
EN3	1	1	I	Input control for channel 3 activation; internal pulldown.
EN4	2	2	I	Input control for channel 4 activation; internal pulldown.
NC	8, 21, 16	8, 21, 16	—	No internal connection.
ST1	3	—	O	Open-drain diagnostic status output for channel 1.
ST2	4	—	O	Open-drain diagnostic status output for channel 2.
ST3	5	—	O	Open-drain diagnostic status output for channel 3.
ST4	6	—	O	Open-drain diagnostic status output for channel 4.
SEH	—	3	I	CS channel-selection high bit; internal pulldown.
SEL	—	4	I	CS channel-selection low bit; internal pulldown.
THER	10	10	I	Thermal shutdown behavior control, latch off or auto-retry; internal pulldown.
OUT1	24, 25	24, 25	O	Output of the channel 1 high side-switch, connect to the load.
OUT2	22, 23	22, 23	O	Output of the channel 2 high side-switch, connect to the load.

**表 6-1. Pin Functions (continued)**

PIN			I/O	DESCRIPTION
NAME	TPS274160			
	Version A	Version B		
OUT3	14, 15	14, 15	O	Output of the channel 3 high side-switch, connect to the load.
OUT4	12, 13	12, 13	O	Output of the channel 4 high side-switch, connect to the load.
VS	17, 18, 19, 20	17, 18, 19, 20	I	Power supply.
Thermal pad	—	—	—	Connect to device GND or leave floating

## 7 Specifications

### 7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) <sup>(1)</sup> <sup>(2)</sup>

	MIN	MAX	UNIT
Input Voltage on Supply pin <sup>(3)</sup>		50	V
Reverse polarity voltage <sup>(4)</sup>	–36		V
Current on GND pin	–100	250	mA
t < 2 minutes			
Voltage on ENx, DIAG_EN, SEL, SEH, and THER pins	–0.3	7	V
Current on ENx, DIAG_EN, SEL, SEH, and THER pins	–10	—	mA
Voltage on $\overline{STx}$ or FAULT pins	–0.3	7	V
Current on $\overline{STx}$ or FAULT pins	–30	10	mA
Voltage on CS pin	–2.7	7	V
Current on CS pin	—	30	mA
Voltage on CL pin	–0.3	7	V
Current on CL pin	—	6	mA
Operating junction temperature	–40	150	°C
Storage temperature, T <sub>stg</sub>	–65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values are with respect to GND.
- (3) Maximum voltage including long transients < 400 ms.
- (4) Reverse polarity condition: time t < 180s, reverse current < I<sub>R(2)</sub>, ENx = 0 V, GND pin 1-kΩ resistor in parallel with diode.

### 7.2 ESD Ratings

			VALUE	UNIT
V <sub>(ESD1)</sub>	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	±2000	V
V <sub>(ESD2)</sub>	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	±5000	V
V <sub>(ESD3)</sub>	Electrostatic discharge	Charged device model (CDM), per JEDEC specification JESD22-C101, all pins <sup>(2)</sup>	±750	V
V <sub>(ESD4)</sub>	Electrostatic discharge	Contact/Air discharge, per IEC 61000-4-2 <sup>(3)</sup>	±8/±15	kV
V <sub>(surge)</sub>	Transient surge	Surge protection with 42 Ω, per IEC 61000-4-5; 1.2/50 μs <sup>(3)</sup>	±1000	V

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.
- (3) Tested with the application circuit and supply voltage of 24 V DC and always ON, EN Inputs High → Output High (ON)

### 7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
$V_{VS}$	Continuous DC Supply operating voltage <sup>(1)</sup>	5	36	V
	Voltage on ENx, DIAG_EN, SEL, SEH, and THER pins	0	5	V
	Voltage on ST and FAULT pins	0	5	V
$I_{nom}$	Nominal DC load current per channel (all channels on)	0	1.35	A
$T_A$	Operating ambient temperature range	-40	125	°C

(1) Transients up to the absolute maximum is allowed

### 7.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		TPS274160	UNIT
		RLH(QFN)	
		28 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	31.7	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	17.3	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	9.6	°C/W
$\Psi_{JT}$	Junction-to-top characterization parameter	0.4	°C/W
$\Psi_{JB}$	Junction-to-board characterization parameter	9.6	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	0.7	°C/W

 (1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).

### 7.5 Electrical Characteristics

 (5 V ≤  $V_S$  ≤ 36 V; -40°C ≤  $T_J$  ≤ 125°C, unless otherwise specified)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$V_{VS(uvr)}$	Undervoltage turnon	$V_S$ voltage rising, $V_{VS} > V_{VS(uvr)}$ , device turns on.	3.5	3.7	4	V
$V_{VS(uvf)}$	Undervoltage shutdown	$V_S$ voltage falling, $V_{VS} < V_{VS(uvf)}$ device shuts off.	3	3.2	3.4	V
$V_{VS(uv,hys)}$	Undervoltage shutdown, hysteresis			0.5		V
$I_{qd}$	Device quiescent current, diagnostics enabled	$V_{VS} < 30$ V, ENx = 5 V, DIAG_EN = H/L, $I_{outx} = 0$ A, current limit = 2 A, all channels on			6.2	mA
$I_{off}$	Standby current	$V_{VS} < 30$ V, ENx = DIAG_EN = OUTx = THER = 0 V, $T_J = 25^\circ\text{C}$			1.4	μA
		$V_{VS} < 30$ V, ENx = DIAG_EN = OUTx = THER = 0 V, $T_J = 125^\circ\text{C}$			5	
$I_{off(diag)}$	Standby current with diagnostic enabled	$V_{VS} < 30$ V, ENx = 0 V, DIAG_EN = 5 V, $V_{VS} - V_{OUTx} > V_{ol(off)}$ , not in open-load mode			5	mA
$t_{off(deg)}$	Standby mode deglitch time <sup>(1)</sup>	EN from high to low, if elapsed time > $t_{off(deg)}$ , the device enters into standby mode.	10	12.5	15	ms
$I_{out(leak)}$	Output leakage current in off-state	$V_{VS} < 30$ V, ENx = DIAG_EN = OUTx = 0, $T_J = 25^\circ\text{C}$			0.5	μA
		$V_{VS} < 30$ V, ENx = DIAG_EN = OUTx = 0, $T_J < 125^\circ\text{C}$			8	μA
$r_{DS(on)}$	On-state resistance	$V_{VS} \geq 5$ V, $T_J = 25^\circ\text{C}$		160		mΩ
		$V_{VS} \geq 5$ V, $T_J = 125^\circ\text{C}$			260	
$\Delta r_{DS(on)}$	Percentage Difference in On-state resistance between channels ( $r_{DS(on)CHx} - r_{DS(on)CHy}$ ) <sup>(1)</sup>	$V_{VS} \geq 5$ V, $T_J = 25^\circ\text{C}$			6	%
$I_{cl(int)}$	Internal current limit	Internal current limit value, CL pin connected to GND	8		14	A
$I_{cl(TSD)}$	Current limit during thermal shutdown	Internal current limit value under thermal shutdown		6.5		A
		External current limit value under thermal shutdown. The percentage of the external current limit setting value			70%	

## 7.5 Electrical Characteristics (continued)

(5 V ≤ V<sub>S</sub> ≤ 36 V; -40°C ≤ T<sub>J</sub> ≤ 125°C, unless otherwise specified)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V <sub>ds(clamp)</sub>	Source-to-drain body diode voltage		50		70	V
V <sub>F</sub>	Drain-source diode voltage	EN = 0, I <sub>out</sub> = -0.15 A.	0.3	0.7	0.9	V
I <sub>R(1)</sub>	Continuous reverse current from source to drain	t < 60 s, V <sub>VS</sub> = 24 V, EN <sub>x</sub> = 0 V, T <sub>J</sub> = 25°C, single channel reversed current to supply		2.5		A
I <sub>R(2)</sub>	Continuous reverse current from source to drain	t < 60 s, V <sub>VS</sub> = 24 V, EN <sub>x</sub> = 0 V, GND pin 1-kΩ resistor in parallel with diode. T <sub>J</sub> = 25°C. Reverse-current condition, All channels reversed		2.0		A
V <sub>IH</sub>	Logic high-level voltage		2			V
V <sub>IL</sub>	Logic low-level voltage				0.8	V
R <sub>(logic,pd)</sub>	Logic-pin pulldown resistor	DIAG_EN V <sub>VS</sub> = V <sub>DIAG_EN</sub> =5V	200	275	350	kΩ
R <sub>(logic,pd)</sub>	Logic-pin pulldown resistor	EN <sub>x</sub> , SEL, SEH, THER pins, V <sub>VS</sub> = V <sub>EN<sub>x</sub></sub> = V <sub>SEL</sub> =V <sub>SEH</sub> =V <sub>THER</sub> =5V	100	175	250	kΩ
I <sub>gnd(loss)</sub>	Output leakage current under GND loss condition	V <sub>VS</sub> = 24 V			20	μA
V <sub>ol(off)</sub>	Open load detection threshold	EN <sub>x</sub> = 0 V, when V <sub>VS</sub> - V <sub>OUT<sub>x</sub></sub> > V <sub>ol(off)</sub> , duration longer than t <sub>ol(off)</sub> , then open load is detected, off state	1.6		2.6	V
t <sub>ol(off)</sub>	Open-load detection threshold deglitch time	EN <sub>x</sub> = 0V, when V <sub>VS</sub> - V <sub>OUT<sub>x</sub></sub> > V <sub>ol(off)</sub> , duration longer than t <sub>ol(off)</sub> , then open load is detected, off state	300	560	800	μs
I <sub>ol(off)</sub>	Off-state output sink current	EN <sub>x</sub> = 0 V, DIAG_EN = 5 V, V <sub>VS</sub> - V <sub>OUT<sub>x</sub></sub> = 24 V, T <sub>J</sub> = 125°C, open load			100	μA
V <sub>OL(STx)</sub>	Status low-output voltage	I <sub>STx</sub> = 2 mA, version A only			0.2	V
V <sub>OL(FAULT)</sub>	Fault low-output voltage	I <sub>FAULT</sub> = 2 mA, version B only			0.2	V
t <sub>cl(deg)</sub>	Deglitch time when current limit occurs(1)	EN <sub>x</sub> = DIAG_EN = 5 V, the deglitch time from current limit toggling to FAULT, STx, CS report.	80		180	μs
T <sub>SD</sub>	Thermal shutdown threshold		160	175		°C
T <sub>SD(rst)</sub>	Thermal shutdown status reset threshold			155		°C
T <sub>sw</sub>	Thermal swing shutdown threshold			60		°C
T <sub>hys</sub>	Hysteresis for resetting the thermal shutdown or thermal swing			10		°C
K <sub>CS</sub>	Current sense ratio (Ver. B only)			300		
K <sub>CL</sub>	Current limit ratio			2500		
V <sub>CL(th)</sub>	Current limit internal threshold voltage <sup>(1) (2)</sup>			0.8		V
dK <sub>CS</sub> / K <sub>CS</sub>	Current sense accuracy, (I <sub>CS</sub> × K <sub>CS</sub> - I <sub>OUT</sub> ) / I <sub>OUT</sub> × 100	V <sub>VS</sub> = 24 V, I <sub>outx</sub> ≥ 5 mA (Version B)	-50		50	%
dK <sub>CS</sub> / K <sub>CS</sub>	Current sense accuracy, (I <sub>CS</sub> × K <sub>CS</sub> - I <sub>OUT</sub> ) / I <sub>OUT</sub> × 100	V <sub>VS</sub> = 24 V, I <sub>outx</sub> ≥ 25 mA (Version B)	-10		10	%
dK <sub>CS</sub> / K <sub>CS</sub>	Current sense accuracy, (I <sub>CS</sub> × K <sub>CS</sub> - I <sub>OUT</sub> ) / I <sub>OUT</sub> × 100	V <sub>VS</sub> = 24 V, I <sub>outx</sub> ≥ 50 mA (Version B)	-5		5	%
dK <sub>CS</sub> / K <sub>CS</sub>	Current sense accuracy, (I <sub>CS</sub> × K <sub>CS</sub> - I <sub>OUT</sub> ) / I <sub>OUT</sub> × 100	V <sub>VS</sub> = 24 V, I <sub>outx</sub> ≥ 100 mA (Version B)	-3		3	%
dK <sub>CS</sub> / K <sub>CS</sub>	Current sense accuracy, (I <sub>CS</sub> × K <sub>CS</sub> - I <sub>OUT</sub> ) / I <sub>OUT</sub> × 100	V <sub>VS</sub> = 24 V, I <sub>outx</sub> ≥ 0.5 A (Version B)	-2		2	%
dK <sub>CL</sub> / K <sub>CL</sub>	External current limit accuracy, (I <sub>OUT</sub> - I <sub>CL</sub> × K <sub>CL</sub> -) × 100 / I <sub>CL</sub> × K <sub>CL</sub>	V <sub>VS</sub> = 24 V, I <sub>limit</sub> ≥ 0.25 A	-20		20	%

## 7.5 Electrical Characteristics (continued)

(5 V ≤ V<sub>S</sub> ≤ 36 V; -40°C ≤ T<sub>J</sub> ≤ 125°C, unless otherwise specified)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
dK <sub>CL</sub> / K <sub>CL</sub>	External current limit accuracy, ( I <sub>OUT</sub> - I <sub>CL</sub> × K <sub>CL</sub> - ) × 100 / I <sub>CL</sub> × K <sub>CL</sub>	V <sub>VS</sub> = 24 V, 2 A ≤ I <sub>limit</sub> ≤ 7 A	-15		15	%
V <sub>CS(lin)</sub>	Current-sense voltage linear range <sup>(1)</sup>	V <sub>VS</sub> ≥ 6.5 V	0		4	V
		5 V ≤ V <sub>VS</sub> < 6.5 V	0	V <sub>S</sub> - 2.5	2.5	
I <sub>OUTX(lin)</sub>	Output-current linear range <sup>(1)</sup>	V <sub>VS</sub> ≥ 6.5 V, V <sub>cs,lin</sub> ≤ 4 V	0		2.2	A
		5 V ≤ V <sub>VS</sub> < 6.5 V, V <sub>cs,lin</sub> ≤ V <sub>VS</sub> - 2.5 V	0		2.2	
V <sub>CS(H)</sub>	Current sense pin output voltage	V <sub>VS</sub> ≥ 7 V, fault mode	4.5		6.5	V
		5 V ≤ V <sub>VS</sub> < 7 V, fault mode	Min(V <sub>S</sub> - 2, 4.5)		6.5	V
I <sub>CS(H)</sub>	Current-sense pin output current available in fault mode	V <sub>cs</sub> = 4.5 V, V <sub>VS</sub> > 7 V	15			mA
I <sub>CS(leak)</sub>	Current-sense leakage current in disabled mode	DIAG_EN = 0 V, T <sub>J</sub> = 125°C			0.5	μA

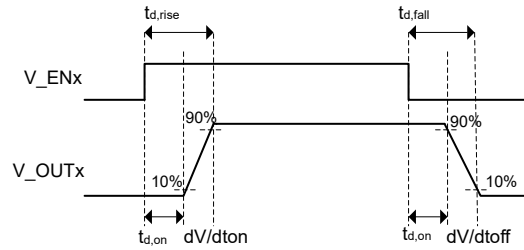
(1) Value specified by design, not subject to production test.

(2) V<sub>cl,th</sub> tolerance is included in the dK<sub>CL</sub> / K<sub>CL</sub> tolerance.

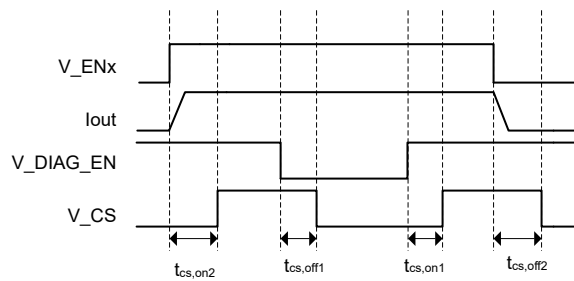
## 7.6 Switching Characteristics

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t <sub>d,on</sub>	Turnon delay time	V <sub>S</sub> = 24 V, DIAG_EN = 5 V, I <sub>outx</sub> = 0.5 A, IN rising edge to 10% of V <sub>outx</sub>	20	50	90	μs
t <sub>d,off</sub>	Turnoff delay time	V <sub>S</sub> = 24 V, DIAG_EN = 5 V, I <sub>outx</sub> = 0.5 A, IN falling edge to 90% of V <sub>outx</sub>	20	50	90	μs
t <sub>d,rise</sub>	Channel turnon time	V <sub>S</sub> = 24 V, DIAG_EN = 5 V, I <sub>outx</sub> = 0.5 A 50% of EN to 90% of V <sub>OUT</sub>	90	120	150	μs
t <sub>d,fall</sub>	Channel Turnoff time	V <sub>S</sub> = 24 V, DIAG_EN = 5 V, I <sub>outx</sub> = 0.5 A 50% of EN to 10% of V <sub>OUT</sub>	90	120	150	μs
dV/dton	Turnon slew rate	V <sub>S</sub> = 24 V, DIAG_EN = 5 V, I <sub>outx</sub> = 0.5 A, V <sub>outx</sub> from 10% to 90%	0.1	0.3	0.55	V/μs
dV/dtoff	Turnoff slew rate	V <sub>S</sub> = 24 V, DIAG_EN = 5 V, I <sub>outx</sub> = 0.5 A, V <sub>outx</sub> from 90% to 10%	0.1	0.3	0.55	V/μs
t <sub>d,match</sub>	t <sub>d,rise</sub> - t <sub>d,fall</sub>	V <sub>S</sub> = 24 V, I <sub>load</sub> = 0.5A. t <sub>d,rise</sub> is the IN rising edge to V <sub>out</sub> = 90%. t <sub>d,fall</sub> is the IN falling edge to V <sub>out</sub> = 10%.	-50		50	μs
t <sub>cs,off1</sub>	CS settling time from DIAG_EN disabled	V <sub>S</sub> = 24 V, EN <sub>x</sub> = 5 V, I <sub>outx</sub> = 0.5 A. current limit = 2 A. DIAG_EN falling edge to 10% of V <sub>cs</sub> .			20	μs
t <sub>cs,on1</sub>	CS settling time from DIAG_EN enabled	V <sub>S</sub> = 24 V, EN <sub>x</sub> = 5 V, I <sub>outx</sub> = 0.5 A. current limit is 2A. DIAG_EN rising edge to 90% of V <sub>cs</sub> .			20	μs
t <sub>cs,off2</sub>	CS settling time from IN falling edge	V <sub>S</sub> = 24 V, DIAG_EN = 5 V, I <sub>outx</sub> = 0.5 A. current limit = 2 A. EN falling edge to 10% of V <sub>cs</sub>			100	μs
t <sub>cs,on2</sub>	CS settling time from IN rising edge	V <sub>S</sub> = 24 V, DIAG_EN = 5 V, I <sub>outx</sub> = 0.5 A. current limit = 2 A. EN rising edge to 90% of V <sub>cs</sub>			150	μs
t <sub>SEx</sub>	Multi-sense transition delay from channel to channel	DIAG_EN = 5 V, current sense output delay when multi-sense pins SEL and SEH transition from channel to channel			50	μs

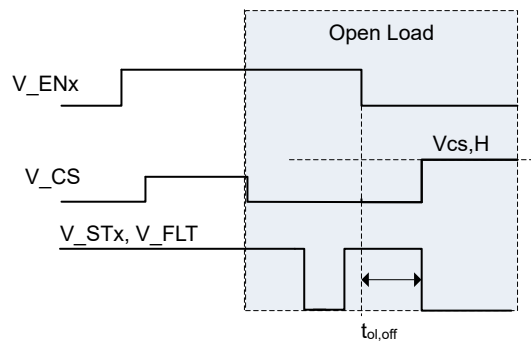




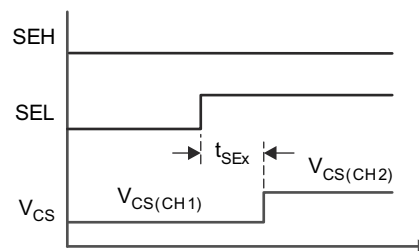
**7-1. Output Delay Characteristics**



**7-2. CS Delay Characteristics**

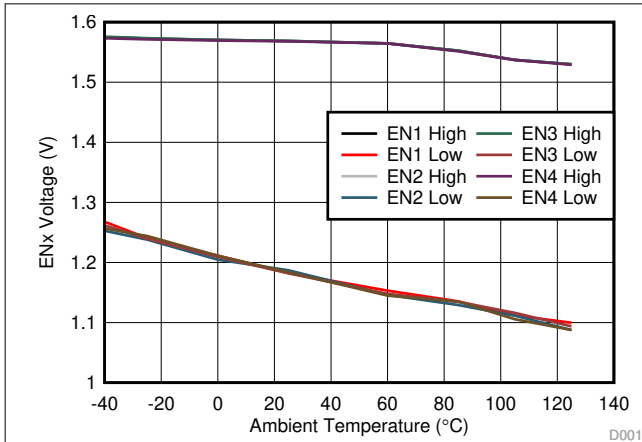


**7-3. Open-Load Blanking-Time Characteristics**

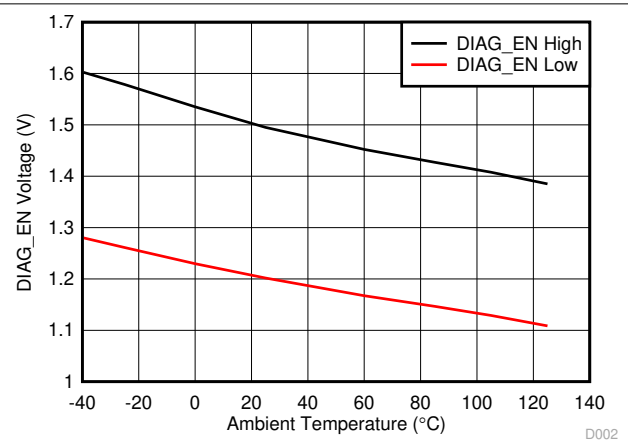


**7-4. Multi-Sense Transition Delay**

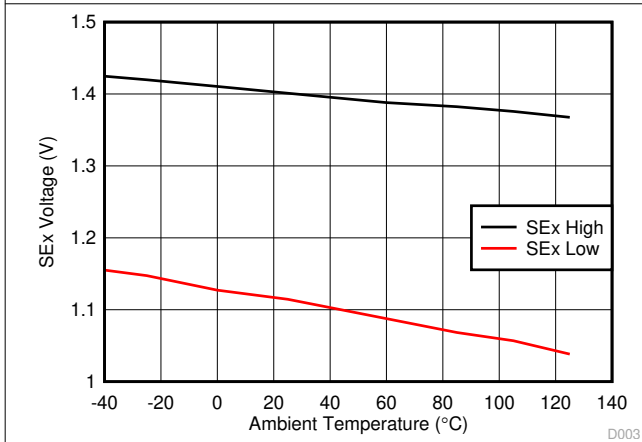
## 7.7 Typical Characteristics



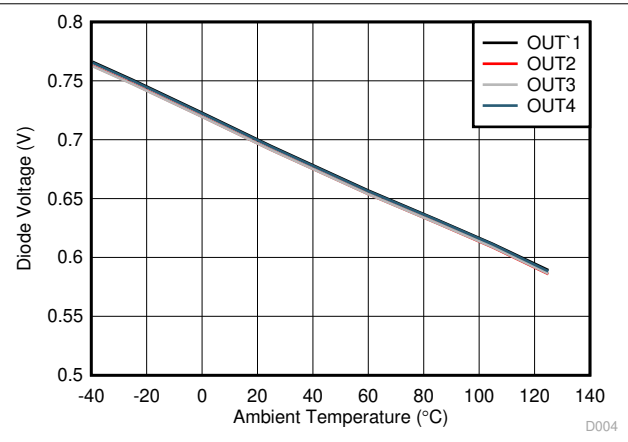
7-5. ENx Voltage Threshold



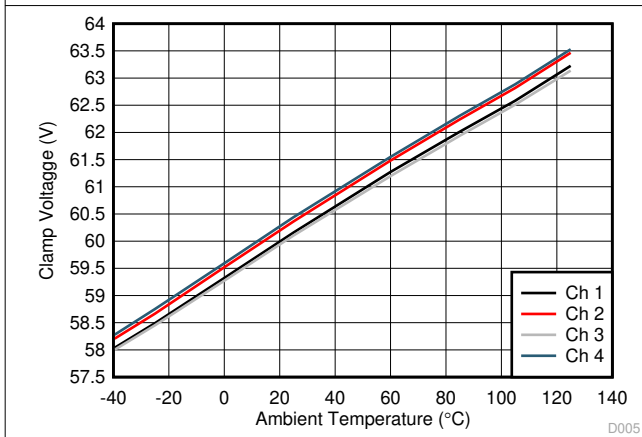
7-6. DIAG\_EN Voltage Threshold



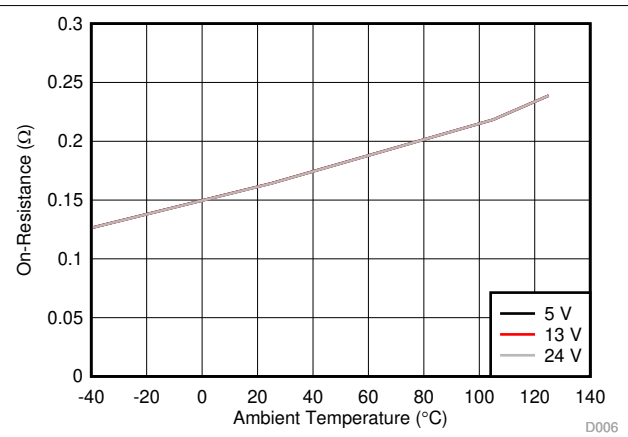
7-7. SEx Voltage Threshold



7-8. Body-Diode Forward Voltage

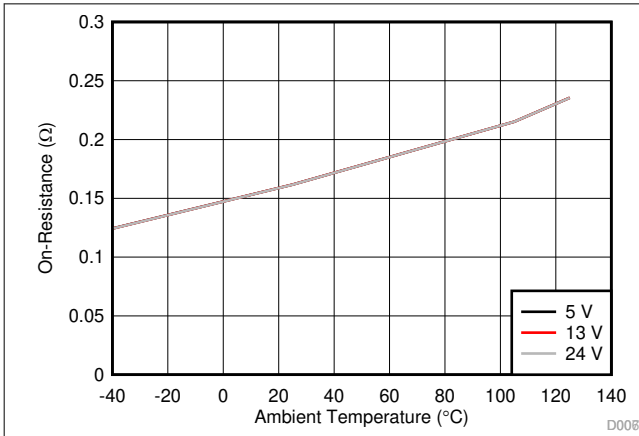


7-9. Drain-to-Source Clamp Voltage

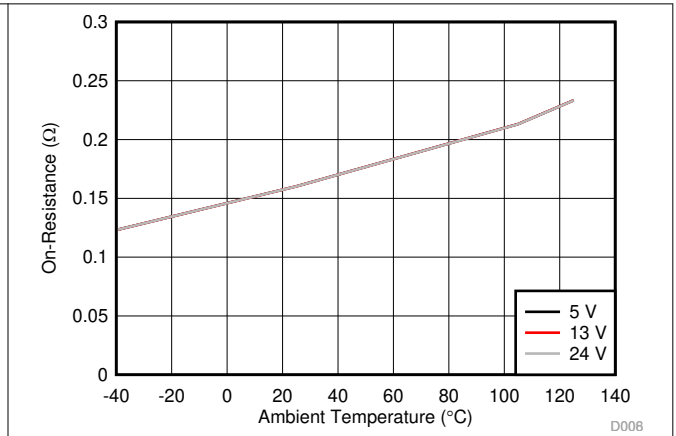


7-10. Channel-1 FET On-Resistance

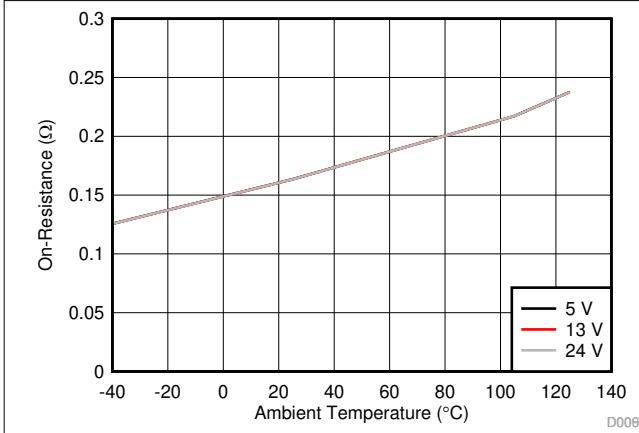
### 7.7 Typical Characteristics (continued)



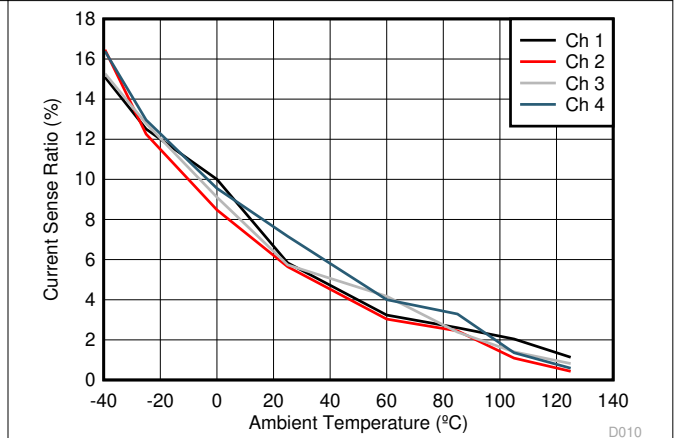
7-11. Channel-2 FET On-Resistance



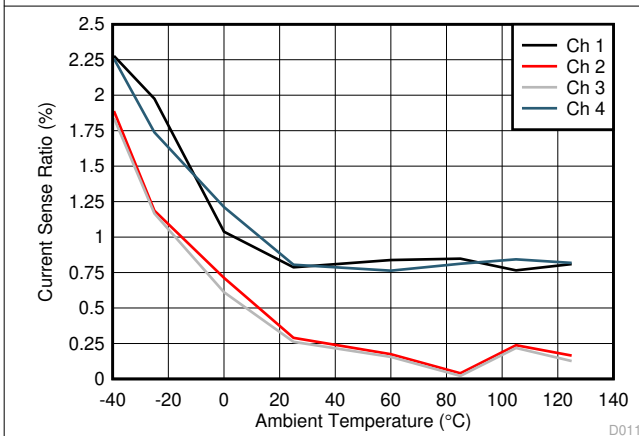
7-12. Channel-3 FET On-Resistance



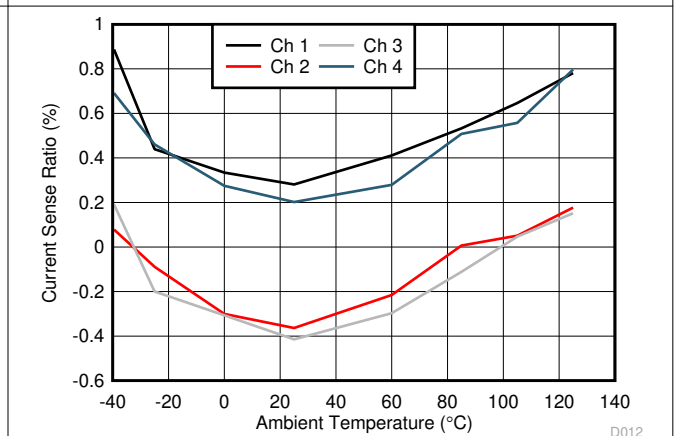
7-13. Channel-4 FET On-Resistance



7-14. Current-Sense Ratio at 5 mA

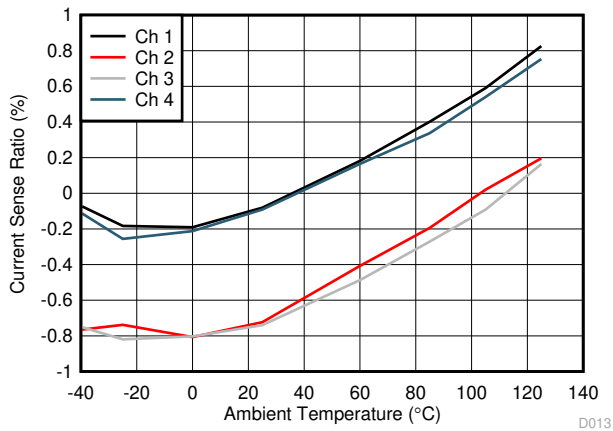


7-15. Current-Sense Ratio at 25 mA

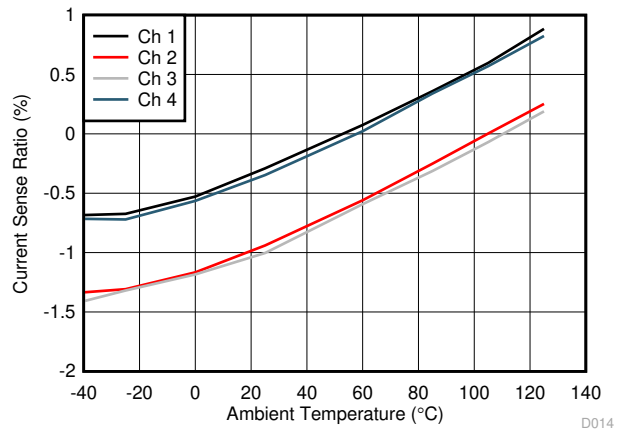


7-16. Current-Sense Ratio at 50 mA

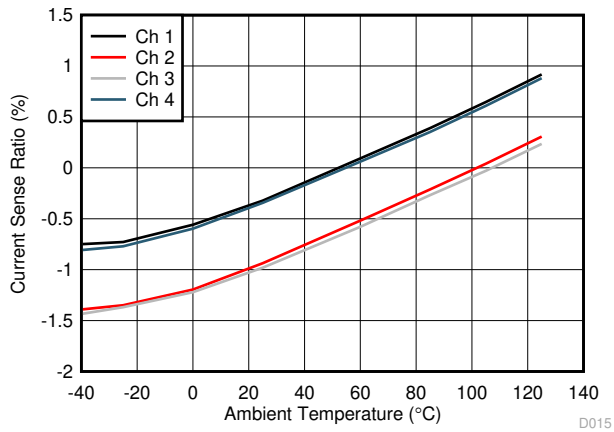
### 7.7 Typical Characteristics (continued)



7-17. Current-Sense Ratio at 100 mA



7-18. Current-Sense Ratio at 500 mA



7-19. Current-Sense Ratio at 1 A

## 8 Detailed Description

### 8.1 Overview

The TPS274160 device is a quad-channel smart high-side switch, with an internal charge pump and NMOS power FETs. The TPS274160 device integrates fault diagnostics and a high-accuracy current-sense feature that enable intelligent control of the load. The adjustable current-limit function greatly improves the reliability of whole system. There are two versions of the device. The TPA274160A contains open drain digital output for diagnostic reporting. The TPS274160B device implements a high accuracy current sense analog output.

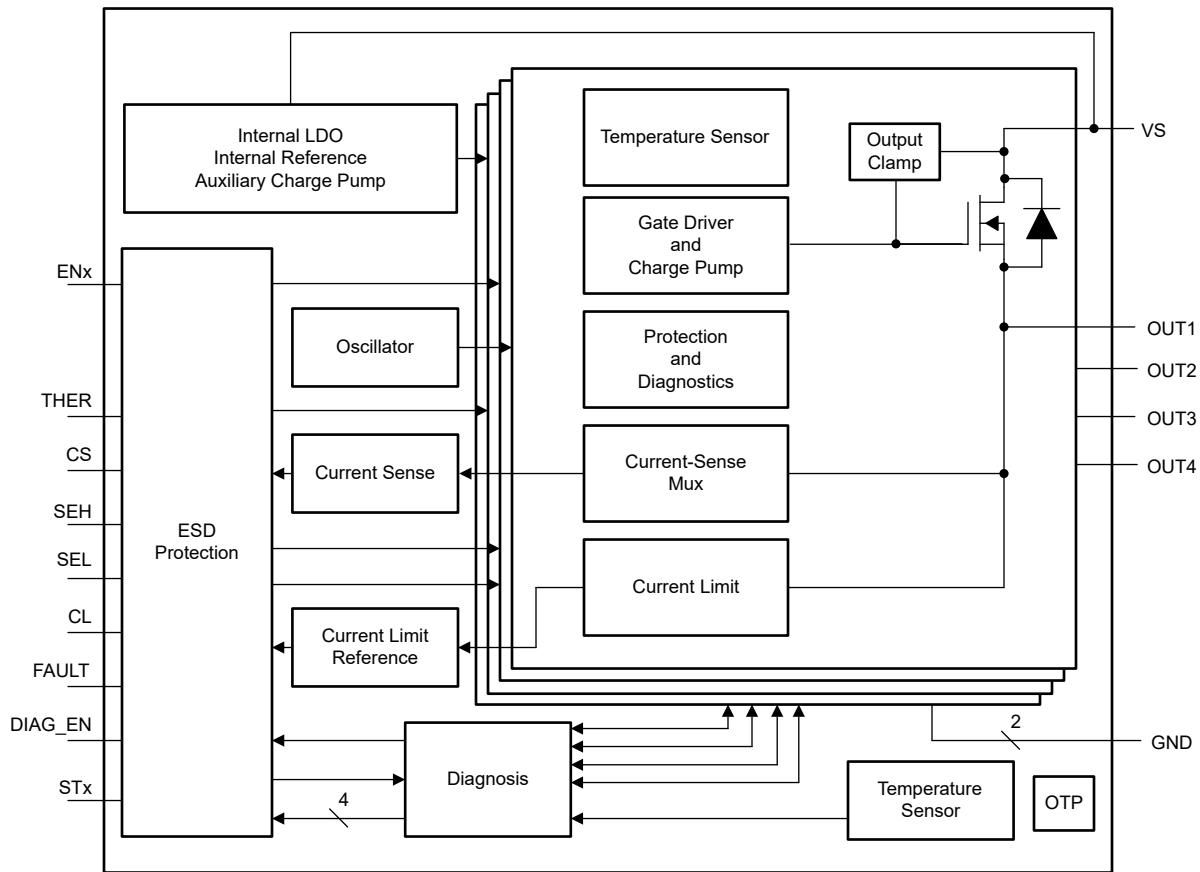
TPS274160A device implements the digital fault report with an open-drain structure. When a fault occurs, the device pulls  $\overline{STx}$  down to GND. A 3.3- or 5-V external pullup is required to match the microcontroller supply level. The digital status of each channel can report individually, or globally by connecting the  $\overline{STx}$  pins together.

The TPS274160B device integrates a high-accuracy current sense circuit that enables precise load current sensing without the need for on-board calibration. The integrated current mirror (selectable one-channel at a time) can source a fraction ( $1 / K_{(CS)}$ ) of the load current. The mirrored current flows into the CS-pin resistor to become a voltage signal.  $K_{(CS)}$  is a near-constant value across temperature and supply voltage. A wide linear region from 0 V to 4 V allows a better real-time load-current monitoring. The CS pin can also report a fault with pullup voltage of  $V_{CS(H)}$ .

The external high-accuracy current limit allows setting the current-limit value by applications. When overcurrent occurs, the device improves system reliability by clamping the inrush current effectively. The device can also save system cost by reducing the size of PCB traces and connectors, and the capacity of the preceding power stage. Besides, the device also implements an internal current limit with a fixed value.

The TPS274160 device integrates active clamp between the drain and the source of the FETs. This clamp ensures that the device is protected during switch off cycle of inductive loads like relays, solenoids and valves. During the inductive load turn-off, the energy of the power supply and the load are dissipated on the high-side switch. The device also optimizes the switching-off slew rate when the clamp is active, which helps the system design by keeping the effects of transient power dissipation and EMI to a minimum.

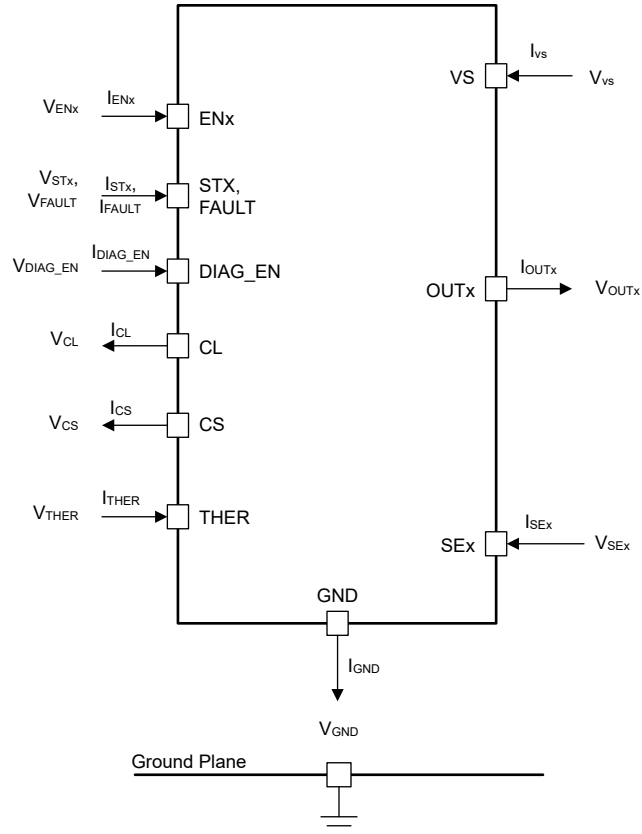
## 8.2 Functional Block Diagram



## 8.3 Feature Description

### 8.3.1 Pin Current and Voltage Conventions

Note that throughout the data sheet, the current directions on the respective pins are as shown by the arrows in [Figure 8-1](#). All voltages are measured relative to the ground plane.

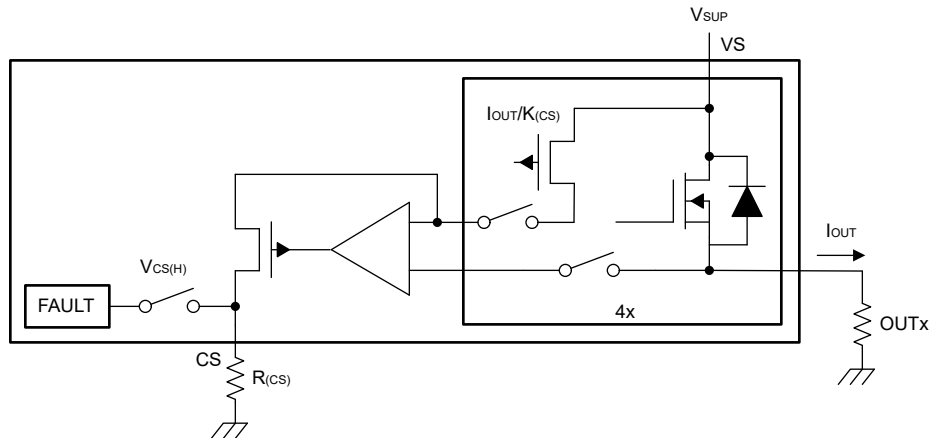


**8-1. Voltage and Current Conventions**

### 8.3.2 Accurate Current Sense

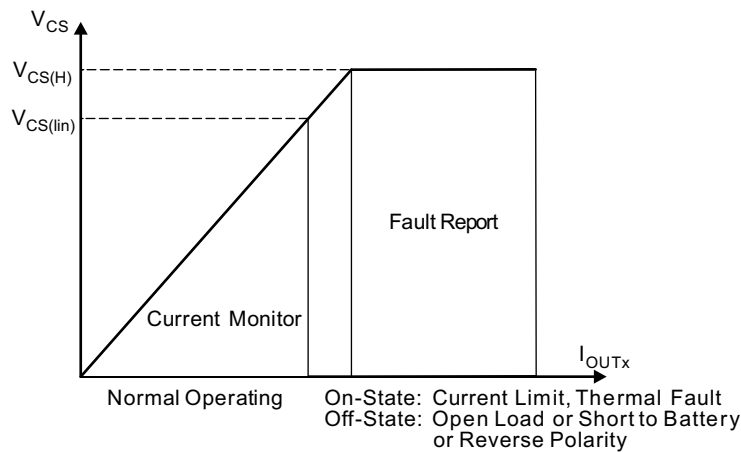
High-accuracy current sense is implemented in the TPS274160B device. This feature enables continuous current monitoring and accurate load diagnostic without extensive calibration.

The integrated current mirror sources  $1 / K_{(CS)}$  of the load current, and the mirrored current flows into the external current sense resistor to become a voltage signal. The current mirror is shared by the four channels.  $K_{(CS)}$  is the ratio of the output current and the sense current. It is a constant value across the temperature and supply voltage. Each device is calibrated accurately during production, so post-calibration is not required. See [8-2](#) for more details.



**8-2. Current-Sense Block Diagram**

When a fault occurs, the CS pin also works as a fault report with a pullup voltage,  $V_{CS(H)}$ . See [8-3](#) for more details.



**8-3. Current-Sense Output-Voltage Curve**

Use [式 1](#) to calculate  $R_{(CS)}$ .

$$R_{(CS)} = \frac{V_{CS}}{I_{CS}} = \frac{V_{CS} \times K_{(CS)}}{I_{OUTx}} \tag{1}$$

Take the following points into consideration when calculating  $R_{(CS)}$ .

- Ensure  $V_{CS}$  is within the current-sense linear region ( $V_{CS}$ ,  $I_{OUTx(lin)}$ ) across the full range of the load current. Check  $R_{(CS)}$  with [式 2](#).

$$R_{(CS)} = \frac{V_{CS}}{I_{CS}} \leq \frac{V_{CS(lin)}}{I_{CS}} \tag{2}$$

- In fault mode, ensure  $I_{CS}$  is within the source capacity of the CS pin ( $I_{CS(H)}$ ). Check  $R_{(CS)}$  with [式 3](#).

$$R_{(CS)} = \frac{V_{CS}}{I_{CS}} \geq \frac{V_{CS(H,min)}}{I_{CS(H,min)}} \tag{3}$$



### 8.3.3 Adjustable Current Limit

A high-accuracy current limit allows high reliability of the design. It protects the load and the power supply from overstressing during short-circuit-to-GND or power-up conditions. The current limit can also save system cost by reducing the size of PCB traces and connectors, and the capacity of the preceding power stage.

When a current-limit threshold is hit, a closed loop activates immediately. The output current is clamped at the set value, and a fault is reported out. The device heats up due to the high power dissipation on the power FET. If thermal shutdown occurs, the current limit is set to  $I_{CL(TSD)}$  to reduce the power dissipation on the power FET. See [8-4](#) for more details.

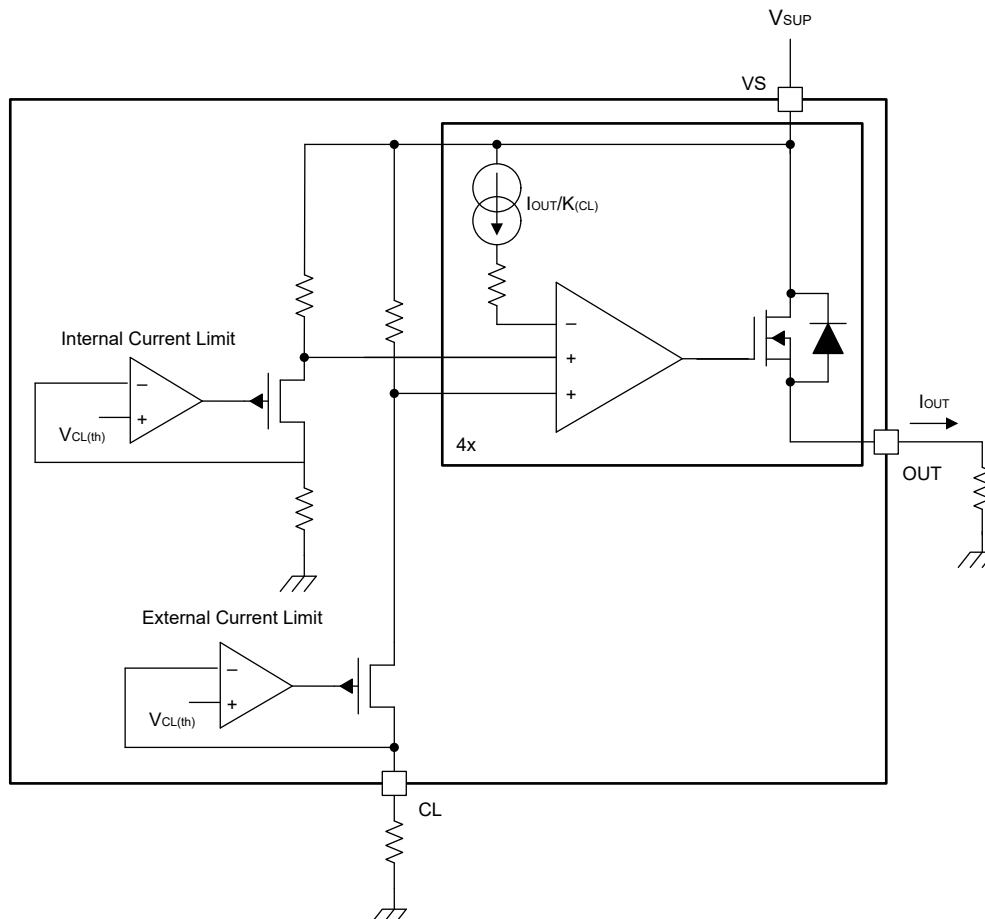
The device has two current-limit thresholds.

- Internal current limit – The internal current limit is fixed at  $I_{CL(int)}$ . Tie the CL pin directly to the device GND for large-transient-current applications.
- External adjustable current limit – An external resistor is used to set the current-limit threshold. Use the [式 4](#) to calculate the  $R_{(CL)}$ .  $V_{CL(th)}$  is the internal band-gap voltage.  $K_{(CL)}$  is the ratio of the output current and the current-limit set value. It is constant across the temperature and supply voltage. The external adjustable current limit allows the flexibility to set the current limit value by applications.

$$I_{CL} = \frac{V_{CL(th)}}{R_{(CL)}} = \frac{I_{OUT}}{K_{(CL)}}$$

$$R_{(CL)} = \frac{V_{CL(th)} \times K_{(CL)}}{I_{OUT}}$$

(4)



8-4. Current-Limit Block Diagram

Note that if using a GND network which causes a level shift between the device GND and board GND, the CL pin must be connected with device GND.

For better protection from a hard short-to-GND condition (when the ENx pins are enabled, a short to GND occurs suddenly), the device implements a fast-trip protection to turn off the related channel before the current-limit closed loop is set up. The fast-trip response time is less than 1  $\mu$ s, typically. With this fast response, the device can achieve better inrush current-suppression performance.

### 8.3.4 Inductive-Load Turn-Off Clamp

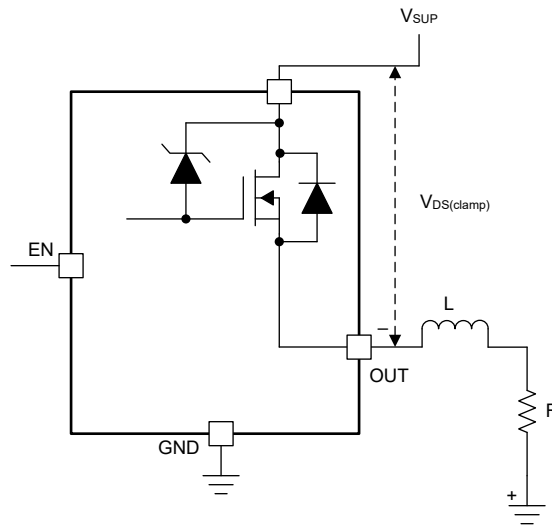
When switching an inductive load off, the inductive reactance tends to pull the output voltage negative. Excessive negative voltage could cause the power FET to break down. To protect the power FET, an internal clamp between drain and source is implemented, namely  $V_{DS(\text{clamp})}$ .

$$V_{DS(\text{clamp})} = V_{VS} - V_{OUT} \quad (5)$$

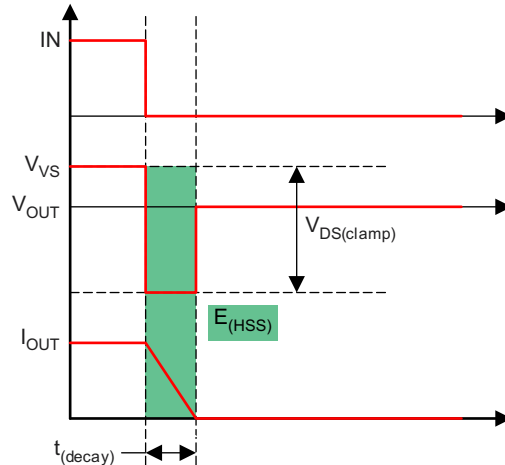
During the period of demagnetization ( $t_{\text{decay}}$ ), the power FET is turned on for inductance-energy dissipation. The inductive load energy is dissipated in the high-side switch. Total energy includes the energy of the power supply ( $E_{(VS)}$ ) and the energy of the load ( $E_{(\text{load})}$ ). If resistance is in series with inductance, some of the load energy is dissipated on the resistance.

$$E_{(\text{HSS})} = E_{(VS)} + E_{(\text{load})} = E_{(VS)} + E_{(L)} - E_{(R)} \quad (6)$$

When an inductive load switches off,  $E_{(\text{HSS})}$  causes a high thermal stress on the device.. The upper limit of the power dissipation depends on the device intrinsic capacity, ambient temperature, and board dissipation condition.



**8-5. Drain-to-Source Clamping Structure**



8-6. Inductive Load Switching-Off Diagram, note EN pin waveform referred to as IN

From the perspective of the high-side switch,  $E_{(HSS)}$  equals the integration value during the demagnetization period.

$$E_{(HSS)} = \int_0^{t_{(decay)}} V_{DS(clamp)} \times I_{OUT}(t) dt$$

$$t_{(decay)} = \frac{L}{R} \times \ln \left( \frac{R \times I_{OUT(max)} + |V_{OUT}|}{|V_{OUT}|} \right)$$

$$E_{(HSS)} = L \times \frac{V_{VS} + |V_{OUT}|}{R^2} \times \left[ R \times I_{OUT(max)} - |V_{OUT}| \ln \left( \frac{R \times I_{OUT(max)} + |V_{OUT}|}{|V_{OUT}|} \right) \right] \quad (7)$$

When R approximately equals 0,  $E_{(HSD)}$  can be given simply as:

$$E_{(HSS)} = \frac{1}{2} \times L \times I_{OUT(max)}^2 \frac{V_{VS} + |V_{OUT}|}{|V_{OUT}|} \quad (8)$$

8-7 is a waveform of the device driving an inductive load. Channel 1 is the EN signal (blue), channel 2 is the supply voltage  $V_{VS}$  (cyan), channel 3 is the output voltage  $V_{OUT}$  (magenta), channel 4 is the output current  $I_{OUT}$  (green), and channel M is the measured power dissipation  $E_{(HSS)}$ .

On the waveform, the duration of  $V_{OUT}$  from  $V_{VS}$  to  $(V_{VS} - V_{DS(clamp)})$  is around 120  $\mu$ s. The device optimizes the switch-off slew rate when the clamp is active. As shown in 8-7, the controlled slew rate is around 0.5 V/ $\mu$ s.

The 8-8 plots the maximum inductive energy ( $E_{AS}$ ) that can be discharged safely by the device a function of the inductor load current in a single pulse in a single channel at one time. If the stored energy in the inductor at the particular load current is higher, then an external clamp will be required.

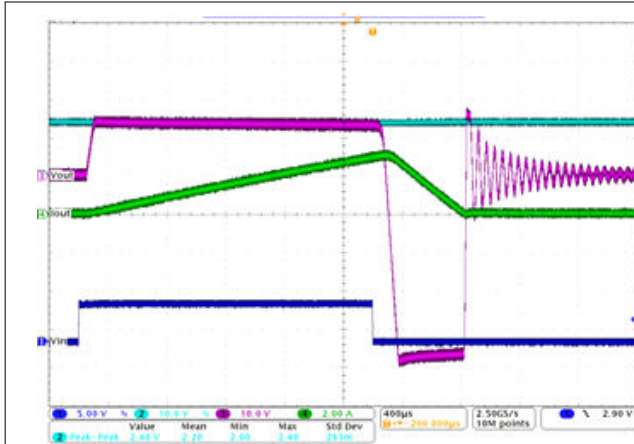


图 8-7. Inductive Load Switching-Off Waveform

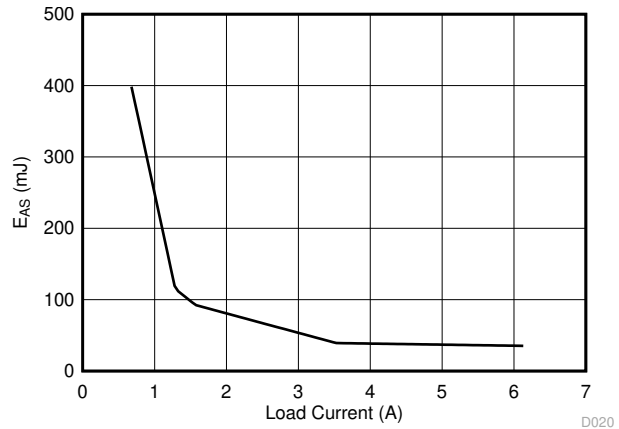


图 8-8. Maximum Energy Dissipation ( $E_{AS}$ ) Allowed  
 $T_{J\_start} = 125^{\circ}\text{C}$  - Single Pulse, One Channel

Note that for PWM-controlled inductive loads, it is recommended to add the external freewheeling circuitry shown in 图 8-9 to protect the device from repetitive power stressing. The TVS clamp is used to achieve the fast decay. See 图 8-9 for more details.

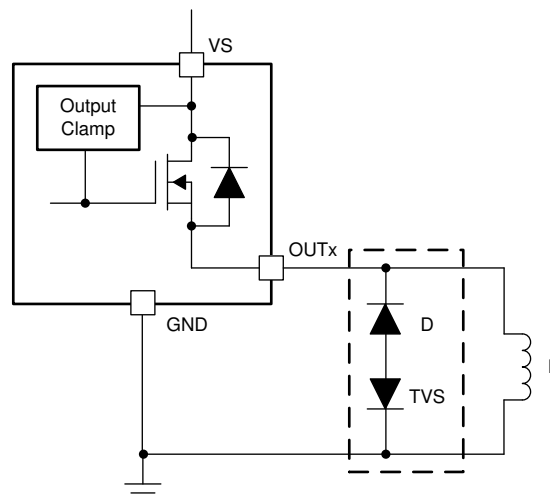


图 8-9. Protection With External Circuitry

### 8.3.5 Fault Detection and Reporting

#### 8.3.5.1 Diagnostic Enable Function

The DIAG\_EN pin enables or disables the diagnostic functions. If multiple devices are used, but the ADC resource is limited in the microcontroller, the MCU can use GPIOs to set DIAG\_EN high to enable the diagnostics of one device while disabling the diagnostics of the other devices by setting DIAG\_EN low. In addition, the device can keep the power consumption to a minimum by setting DIAG\_EN and ENx low.

#### 8.3.5.2 Multiplexing of Current Sense

For version B, SEL and SEH are two pins to multiplex the shared current-sense function among the four channels. See 表 8-1 for more details.

表 8-1. Diagnosis Configuration Table

DIAG_EN	ENx	SEH	SEL	CS ACTIVATED CHANNEL	CS, FAULT, STx	PROTECTIONS AND DIAGNOSTICS
L	H	—	—	—	High impedance	Diagnostics disabled, full protection
	L					Diagnostics disabled, no protection
H	—	0	0	Channel 1	See 表 8-2	See Table 8-2
		0	1	Channel 2		
		1	0	Channel 3		
		1	1	Channel 4		

### 8.3.5.3 Fault Table

表 8-2 applies when the DIAG\_EN pin is enabled.

表 8-2. Fault Table

CONDITIONS	ENx	OUTx	THER	CRITERION	STx (VER. A)	CS (VER. B)	FAULT (VER. B)	FAULT RECOVERY
Normal	L	L	—	—	H	0	H	—
	H	H	—	—	H	In linear region	H	—
Overload, short to ground	H	L	—	Current limit triggered	L	V <sub>CS(H)</sub>	L	Auto
Open load <sup>(1)</sup> , short to supply, reverse polarity	L	H	—	$V_{VS} - V_{OUTx} < V_{(ol,off)}$	L	V <sub>CS(H)</sub>	L	Auto
Thermal shutdown	H	—	L	T <sub>SD</sub> triggered	L	V <sub>CS(H)</sub>	L	Output auto-retry. Fault recovers when T <sub>J</sub> < T <sub>(SD,rst)</sub> or when ENx toggles.
			H					Output latch off. Fault recovers when ENx toggles.
Thermal swing	H	—	—	T <sub>SW</sub> triggered	L	V <sub>CS(H)</sub>	L	Auto

(1) An external pullup is required for open-load detection.

### 8.3.5.4 STx and FAULT Reporting

For version A, four individual STx pins report the fault conditions, each pin for its respective channel. When a fault condition occurs, it pulls STx down to GND. A 3.3- or 5-V external pullup is required to match the supply level of the microcontroller. The digital status of each channel can be reported individually, or globally by connecting all the STx pins together.

For version B, a global FAULT pin is used to monitor the global fault condition among all the channels. When a fault condition occurs on any channel, the FAULT pin is pulled down to GND. A 3.3-V or 5-V external pullup is required to match the supply level of the microcontroller.

After the FAULT report, the microcontroller can check and identify the channel in fault status by multiplexed current sensing. The CS pin also works as a fault report with an internal pullup voltage, V<sub>CS(H)</sub>.

### 8.3.6 Full Diagnostics

#### 8.3.6.1 Short-to-GND and Overload Detection

When a channel is on, a short to GND or overload condition causes overcurrent. If the overcurrent triggers either the internal or external current-limit threshold, the fault condition is reported out. The microcontroller can handle the overcurrent by turning off the switch. The device heats up if no actions are taken. If a thermal shutdown occurs, the current limit is I<sub>CL(TSD)</sub> to keep the power stressing on the power FET to a minimum. The device automatically recovers when the fault condition is removed.

### 8.3.6.2 Open-Load Detection

#### 8.3.6.2.1 Channel On

When a channel is on and an open-load event occurs, it can be detected as an ultra-low  $V_{CS}$  voltage at the CS pin and handled by the micro-controller. The high-accuracy current sense in the low current range, enables the open-load detection at very low current thresholds. Note that the detection is not reported on the STx or FAULT pins. The microcontroller must proactively multiplex the SEL and SEH pins to detect the channel-on open-load fault.

#### 8.3.6.2.2 Channel Off

When a channel is off, if a load is connected, the output is pulled down to GND. But if an open load occurs, the output voltage is close to the supply voltage ( $V_{VS} - V_{OUTx} < V_{(ol,off)}$ ), and the fault is reported out.

There is always a leakage current  $I_{(ol,off)}$  present on the output due to internal logic control path or external humidity, corrosion, and so forth. Thus, TI recommends an external pullup resistor to offset the leakage current when an open load is detected. The recommended pullup resistance is 20 k $\Omega$ .

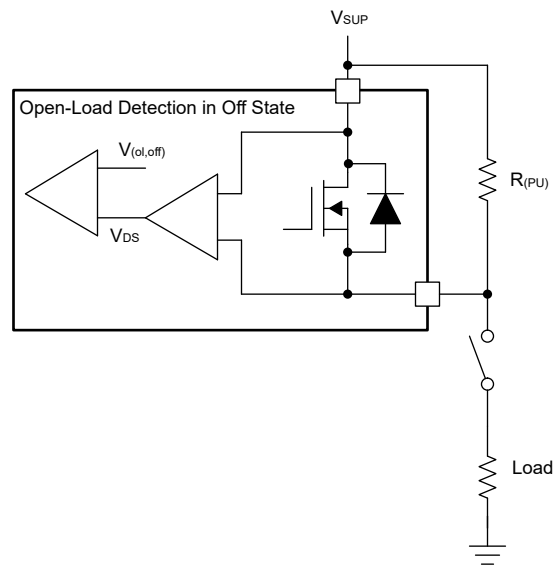


图 8-10. Open-Load Detection in Off-State

#### 8.3.6.3 Short-to-Supply Detection

Short-to-supply has the same detection mechanism and behavior as open-load detection, in both the on-state and off-state. See 表 8-2 for more details.

In the on-state, reverse current flows through the FET instead of the body diode, leading to less power dissipation. Thus, the worst case occurs in the off-state.

- If  $V_{OUTx} - V_{VS} < V_{(F)}$  (body diode forward voltage), no reverse current occurs.
- If  $V_{OUTx} - V_{VS} > V_{(F)}$ , reverse current occurs. The current must be limited to less than  $I_{R(1)}$ . Setting an ENx pin high can minimize the power stress on its channel. Also, for external reverse protection, see [Reverse-Current Protection](#) for more details.

#### 8.3.6.4 Input Reverse Polarity Detection

Reverse polarity detection has the same detection mechanism and behavior as open-load detection both in the on-state and off-state. See 表 8-2 for more details.

In the on-state, the reverse current flows through the FET instead of the body diode, leading to less power dissipation. Thus, the worst case occurs in the off-state. The reverse current must be limited to less than  $I_{R(2)}$ . Set the related ENx pin high to keep the power dissipation to a minimum. For external reverse-blocking circuitry, see [Reverse-Current Protection](#) for more details.

### 8.3.6.5 Thermal Fault Detection

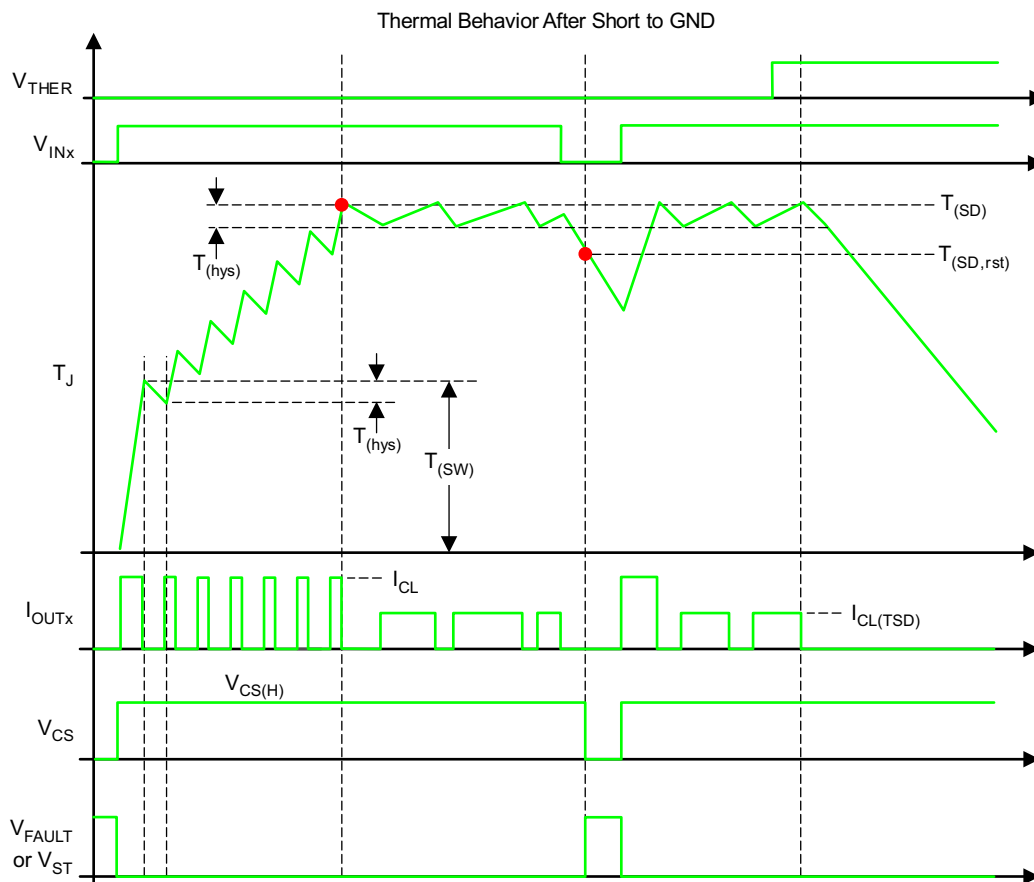
To protect the device in severe power stressing cases, the device implements two types of thermal fault detection, absolute temperature protection (thermal shutdown) and dynamic temperature protection (thermal swing). Respective temperature sensors are integrated close to each power FET, so the thermal fault is reported by each channel. This arrangement can help the device keep the cross-channel effect to a minimum when some channels are in a thermal fault condition.

#### 8.3.6.5.1 Thermal Shutdown

Thermal shutdown is active when the absolute temperature  $T_J > T_{(SD)}$ . When the thermal shutdown occurs, the respective output turns off. The THER pin is used to configure the behavior after the thermal shutdown occurs.

- When the THER pin is low, thermal shutdown operates in the auto-retry mode. The output automatically recovers when  $T_J < T_{(SD)} - T_{(hys)}$ , but the current is limited to  $I_{CL(TSD)}$  to avoid repetitive thermal shutdown. The thermal shutdown fault signal is cleared when  $T_J < T_{(SD,rst)}$  or after toggling the related ENx pin.
- When the THER pin is high, thermal shutdown operates in the latch mode. The output latches off when thermal shutdown occurs. When the THER pin goes from high to low, thermal shutdown changes to auto-retry mode. The thermal shutdown fault signal is cleared after toggling the related ENx pin.

Thermal swing activates when the power FET temperature is increasing sharply, that is, when  $\Delta T = T_{(FET)} - T_{(Logic)} > T_{(sw)}$ , then the output turns off. The output automatically recovers and the fault signal clears when  $\Delta T = T_{(FET)} - T_{(Logic)} < T_{(sw)} - T_{(hys)}$ . Thermal swing function improves the device reliability when subjected to repetitive fast thermal variation. As shown in [Figure 8-11](#), multiple thermal swings are triggered before thermal shutdown occurs.



**Figure 8-11. Thermal Behavior Diagram**

### 8.3.7 Full Protections

#### 8.3.7.1 UVLO Protection

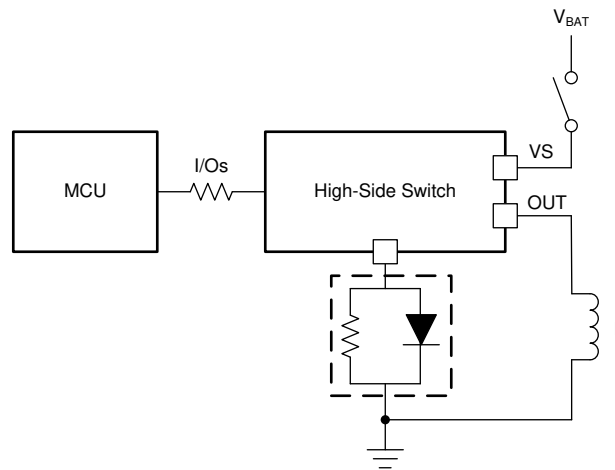
The device monitors the supply voltage  $V_{VS}$ , to prevent unpredicted behaviors when  $V_{VS}$  is too low. When  $V_{VS}$  falls down to  $V_{VS(ufv)}$ , the device shuts down. When  $V_{VS}$  rises up to  $V_{VS(uvr)}$ , the device turns on.

#### 8.3.7.2 Loss-of-GND Protection

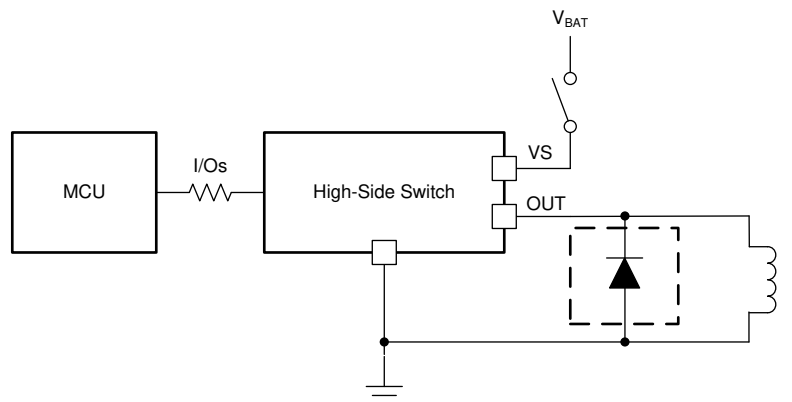
When loss of GND occurs, output is shut down regardless of whether the ENx pin is high or low. The device can protect against two ground-loss conditions, loss of device GND and loss of module GND.

#### 8.3.7.3 Protection for Loss of Power Supply

When loss of supply occurs, the output is shut down regardless of whether the ENx pin is high or low. For a resistive or a capacitive load, loss of supply has no risk. But for a charged inductive load, the current is driven from all the I/O pins to maintain the inductance current. To protect the system in this condition, TI recommends two types of external protections: the GND network or the external free-wheeling diode. In addition, the recommended components per the application diagram needs to be implemented for protection.



8-12. Protection for Loss of Power Supply, Method 1



8-13. Protection for Loss of Power Supply, Method 2

#### 8.3.7.4 Reverse-Current Protection

Reverse current occurs in two conditions: short to supply and reverse polarity.

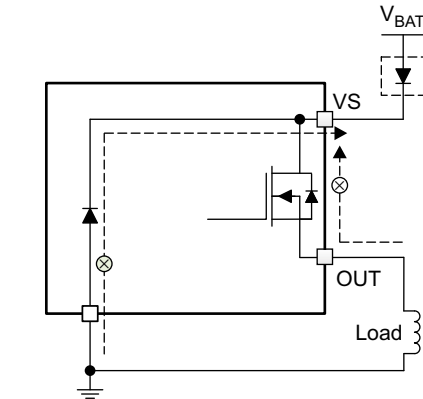
- When a short to the supply occurs, there is only reverse current through the body diode.  $I_{R(1)}$  specifies the limit of the reverse current.



- In a reverse-polarity condition, there are reverse currents through the body diode and the device GND pin.  $I_{R(2)}$  specifies the limit of the reverse current.

To protect the device, TI recommends two types of external circuitry.

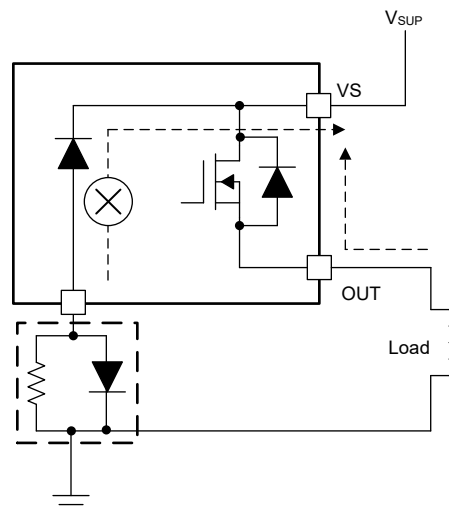
- Adding a blocking diode. Both the IC and load are protected when in reverse polarity.



Copyright © 2016, Texas Instruments Incorporated

#### 8-14. Reverse-Current External Protection, Method 1

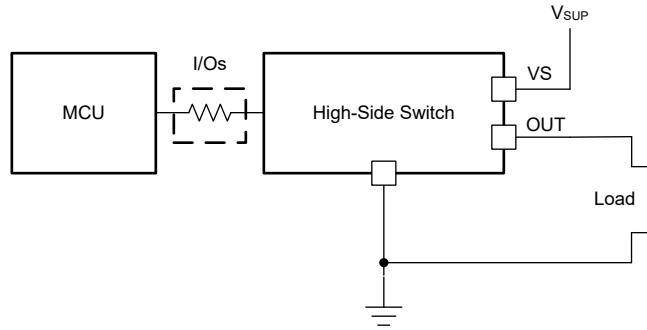
- Adding a GND network. The reverse current through the device GND is blocked. The reverse current through the FET is limited by the load itself. TI recommends a resistor in parallel with the diode as a GND network. The recommended selection are 1-k $\Omega$  resistor in parallel with an > 100-mA diode. If multiple high-side switches are used, the resistor and diode can be shared among devices. The reverse current protection diode in the GND network forward voltage should be less than 0.6 V in any circumstances. In addition a minimum resistance of 4.7 K is recommended on the I/O pins.



#### 8-15. Reverse-Current External Protection, Method 2

### 8.3.7.5 MCU I/O Protection

In some severe conditions, such as the high voltage transients or the loss of supply with inductive loads, a negative pulse occurs on the GND pin. This pulse can cause damage on the connected microcontroller. TI recommends serial resistors to protect the microcontroller, for example, 4.7-k $\Omega$  when using a 3.3-V microcontroller and 10-k $\Omega$  for a 5-V microcontroller.



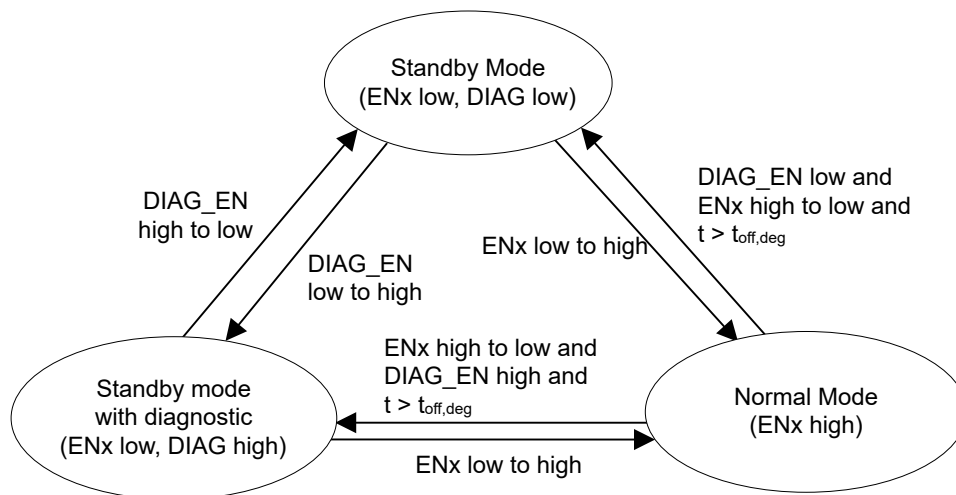
☒ 8-16. MCU I/O External Protection

## 8.4 Device Functional Modes

### 8.4.1 Working Modes

The device has three working modes, the normal mode, the standby mode, and the standby mode with diagnostics.

Note that IN must be low for  $t > t_{(off,deg)}$  to enter the standby mode, where  $t_{(off,deg)}$  is the standby mode deglitch time used to avoid false triggering. ☒ 8-17 shows a working-mode diagram.



☒ 8-17. Working Modes

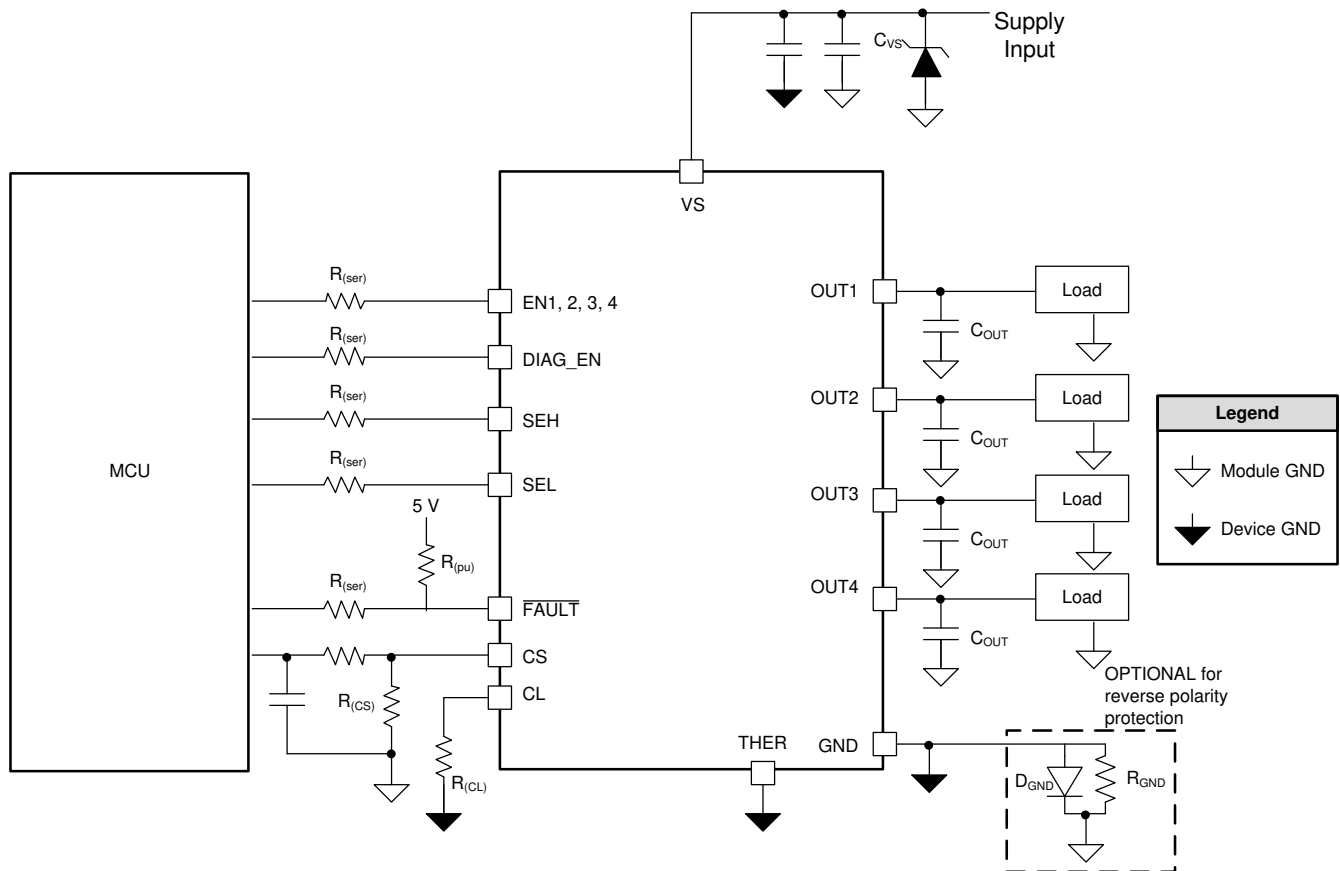
## 9 Application and Implementation

### Note

以下のアプリケーション情報は、TI の製品仕様に含まれるものではなく、TI ではその正確性または完全性を保証いたしません。個々の目的に対する製品の適合性については、お客様の責任で判断していただくこととなります。お客様は自身の設計実装を検証しテストすることで、システムの機能を確認する必要があります。

### 9.1 Application Information

図 9-1 shows the schematic of a typical application of the . It includes all standard external components. This section of the datasheet discusses the considerations in implementing commonly required application functionality.



With the ground protection network, the device ground will be offset relative to the microcontroller ground.

図 9-1. System Diagram

表 9-1. Recommended External Components

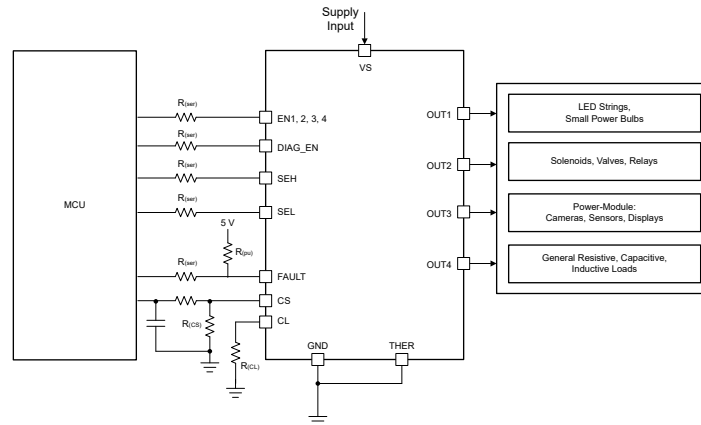
COMPONENT	TYPICAL VALUE	PURPOSE
$R_{(ser)}$	10 k $\Omega$	Protect microcontroller and device I/O pins
$R_{(CS)}$	1 k $\Omega$	Translate the sense current into sense voltage
$C_{SNS}$	100 pF - 10 nF	Low-pass filter for the ADC input
$R_{GND}$	1 k $\Omega$	Stabilize GND potential during turn-off of inductive load
$D_{GND}$	BAS21 Diode	Protects device during reverse supply condition
$R_{(CL)}$	1-k $\Omega$ typical	Set current limiting value, short to IC GND to set the current limit to the internal setting.

**表 9-1. Recommended External Components (continued)**

COMPONENT	TYPICAL VALUE	PURPOSE
$C_{VS}$	10 nF to Device GND and 100 nF to module GND	Filtering of voltage transients (for example, surge)
$Z_{VS}$	TVS to module GND	Clamp voltage spikes at the input.
$C_{OUT}$	22 nF	Filtering of voltage transients (for example, ESD)

## 9.2 Typical Application

The following figure shows example of a typical application based on the TPS274160B device. The loads can be varied and be different on each channel.

**图 9-2. Typical Application Diagram.**

### 9.2.1 Design Requirements

- $V_{VS} = 24\text{-V}$  nominal
- Load range is from 0.1 A to 1 A for each channel
- Current sense for fault monitoring
- Expected current-limit value of 2.5 A
- Automatic recovery mode when thermal shutdown occurs
- Full diagnostics with 5-V MCU

### 9.2.2 Detailed Design Procedure

To keep the 1-A nominal current in the 0 to 4-V current-sense range, calculate the  $R_{(CS)}$  resistor using 式 9. To achieve better current-sense accuracy, a 1% tolerance or better resistor is preferred.

$$R_{(CS)} = \frac{V_{CS}}{I_{CS}} = \frac{V_{CS} \times K_{(CS)}}{I_{OUT}} = \frac{4 \times 300}{1} = 1200 \Omega \quad (9)$$



To set the adjustable current limit value at 2.5-A, calculate  $R_{(CL)}$  using 式 10.

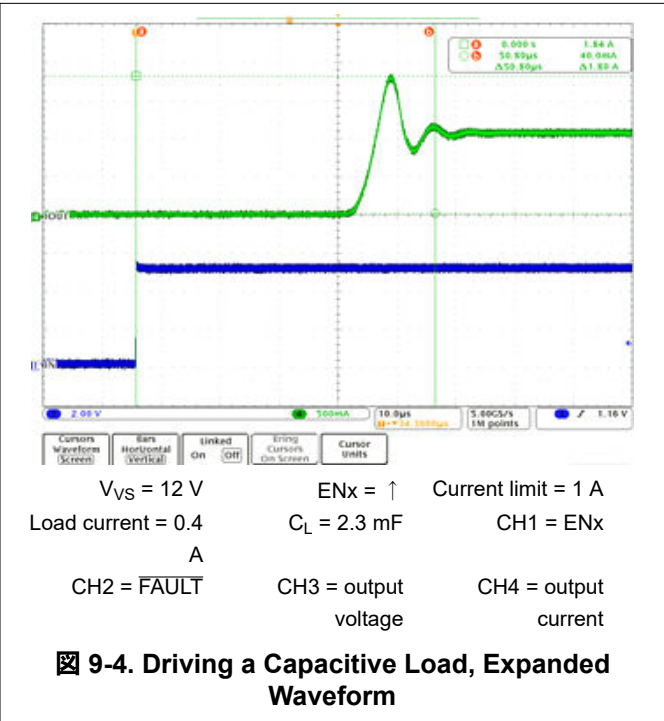
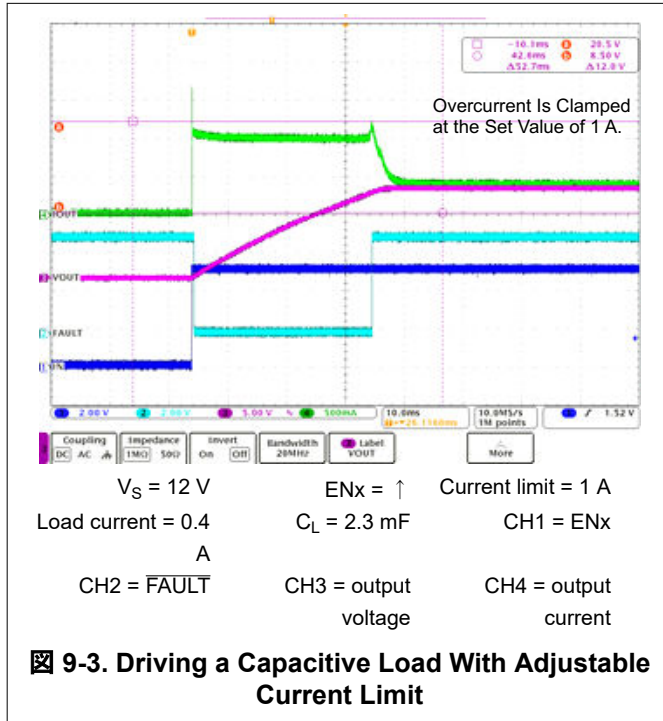
$$R_{(CL)} = \frac{V_{CL(th)} \times K_{(CL)}}{I_{OUT}} = \frac{0.8 \times 2500}{2.5} = 800 \Omega \quad (10)$$

TI recommends  $R_{(ser)} = 10 \text{ k}\Omega$  for 5-V MCU, and  $R_{(pu)} = 10 \text{ k}\Omega$  as the pullup resistor.

## 9.3 Capacitive Load Drive and Application Curves

In this application example we show the case of driving a large capacitive load at the input of a sensor hub supply node. The input capacitance is a 2.3-mF capacitor and is charged to a 12-V supply voltage. The nominal total load current at the node is 0.4 A and the current limit is set to 1 A and chosen to be well in excess of the

peak load current.  9-3 shows a test example of soft-start when driving the large capacitive load.  9-4 shows an expanded waveform of the output current.



## 10 Power Supply Recommendations

The TPS274160 device is designed to operate with a 12-V or 24-V nominal DC supply input. The DC supply voltage range should be within the range specified in the *Recommended Operating Conditions*. The device is also designed to withstand voltage transients beyond this range at the supply input pin up to the absolute maximum voltage specifications.

## 11 Layout

### 11.1 Layout Guidelines

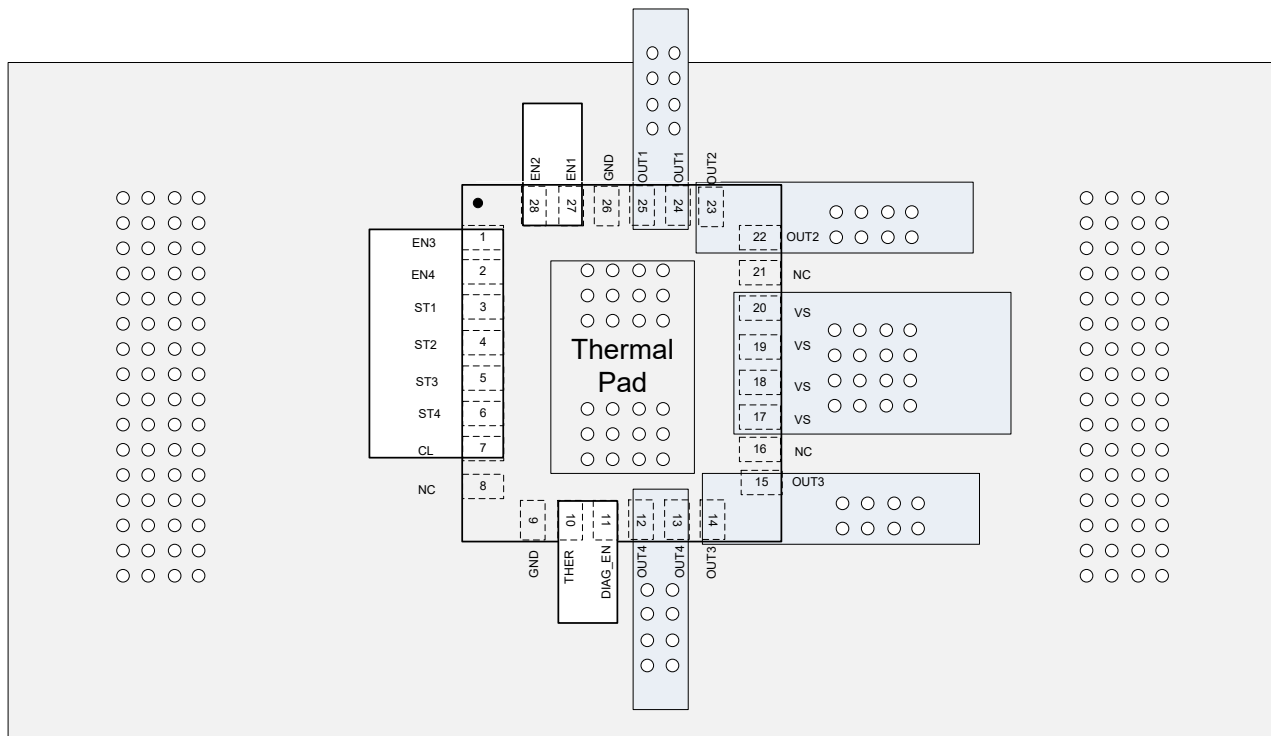
To prevent thermal shutdown,  $T_J$  must be less than  $150^{\circ}\text{C}$ . The WQFN package has good thermal impedance. However, the PCB layout is very important. Good PCB design can optimize heat transfer, which is absolutely essential for the long-term reliability of the device.

- Maximize the copper coverage on the PCB to increase the thermal conductivity of the board. The major heat flow path from the package to the ambient is through the copper on the PCB. Maximum copper is extremely important when there are not any heat sinks attached to the PCB on the other side of the package.
- Add as many thermal vias as possible directly under the package ground pad to optimize the thermal conductivity of the board.
- All thermal vias should either be plated shut or plugged and capped on both sides of the board to prevent solder voids. To ensure reliability and performance, the solder coverage should be at least 85%.

### 11.2 Layout Examples

#### 11.2.1 Without a GND Network

Without a GND network, tie the thermal pad directly to the board GND copper for better thermal performance.



☒ 11-1. Layout Example Without a GND Network

## 12 Device and Documentation Support

### 12.1 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、[ti.com](https://ti.com) のデバイス製品フォルダを開いてください。「更新の通知を受け取る」をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取れます。変更の詳細については、修正されたドキュメントに含まれている改訂履歴をご覧ください。

### 12.2 サポート・リソース

**TI E2E™ サポート・フォーラム**は、エンジニアが検証済みの回答と設計に関するヒントをエキスパートから迅速かつ直接得ることができる場所です。既存の回答を検索したり、独自の質問をしたりすることで、設計に必要な支援を迅速に得ることができます。

リンクされているコンテンツは、該当する貢献者により、現状のまま提供されるものです。これらは TI の仕様を構成するものではなく、必ずしも TI の見解を反映したものではありません。TI の[使用条件](#)を参照してください。

### 12.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.

すべての商標は、それぞれの所有者に帰属します。

### 12.4 静電気放電に関する注意事項



この IC は、ESD によって破損する可能性があります。テキサス・インスツルメンツは、IC を取り扱う際には常に適切な注意を払うことを推奨します。正しい ESD 対策をとらないと、デバイスを破損するおそれがあります。

ESD による破損は、わずかな性能低下からデバイスの完全な故障まで多岐にわたります。精密な IC の場合、パラメータがわずかに変化するだけで公表されている仕様から外れる可能性があるため、破損が発生しやすくなっています。

### 12.5 用語集

**TI 用語集** この用語集には、用語や略語の一覧および定義が記載されています。

## 13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most-current data available for the designated device. This data is subject to change without notice and without revision of this document. For browser-based versions of this data sheet, see the left-hand navigation pane.

**PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">TPS274160ARLHR</a>	Active	Production	WQFN (RLH)   28	3000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	274160A
TPS274160ARLHR.A	Active	Production	WQFN (RLH)   28	3000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	274160A
TPS274160ARLHRG4	Active	Production	WQFN (RLH)   28	3000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	274160A
TPS274160ARLHRG4.A	Active	Production	WQFN (RLH)   28	3000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	274160A
<a href="#">TPS274160BRLHR</a>	Active	Production	WQFN (RLH)   28	3000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	274160B
TPS274160BRLHR.A	Active	Production	WQFN (RLH)   28	3000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	274160B

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

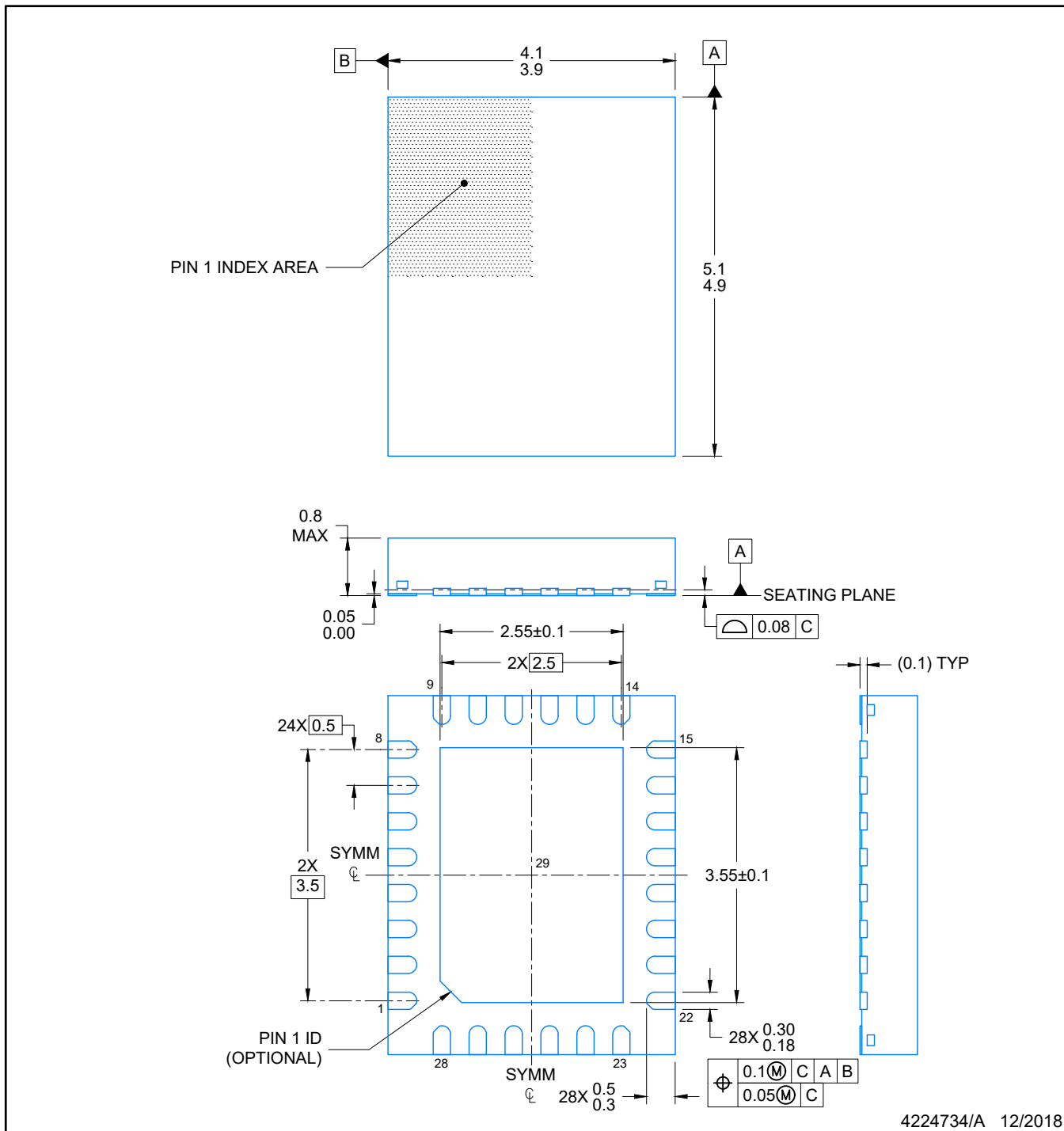
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

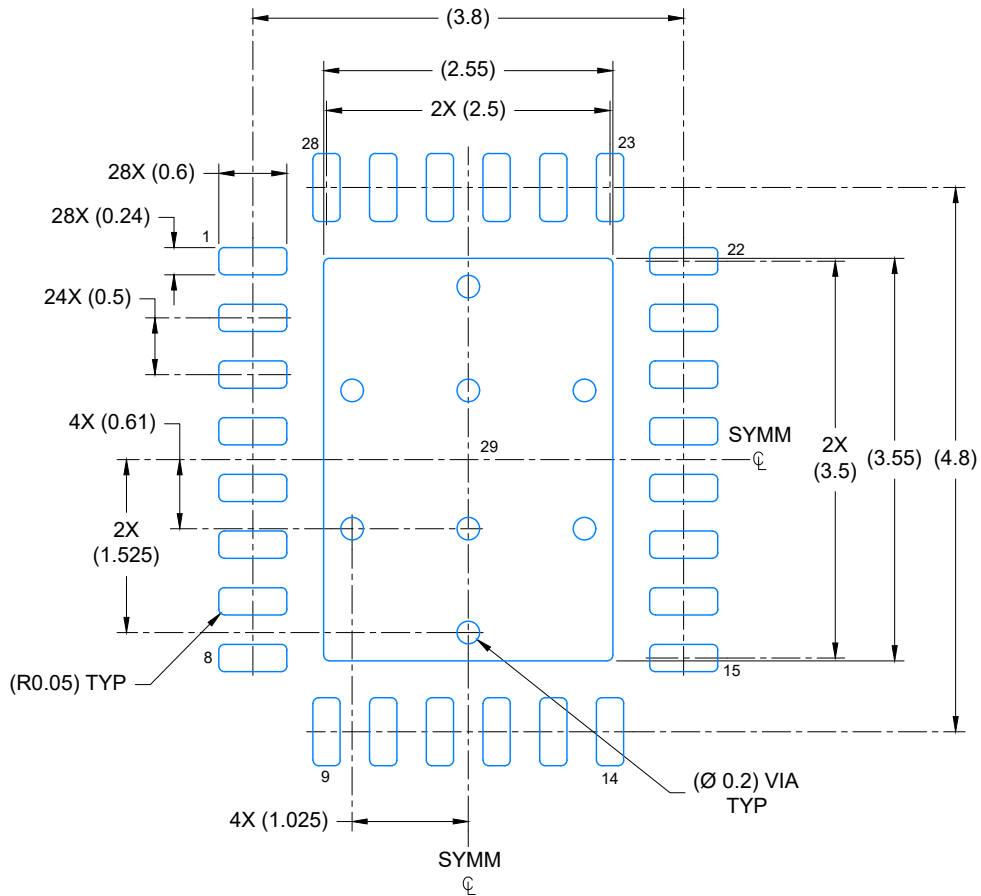




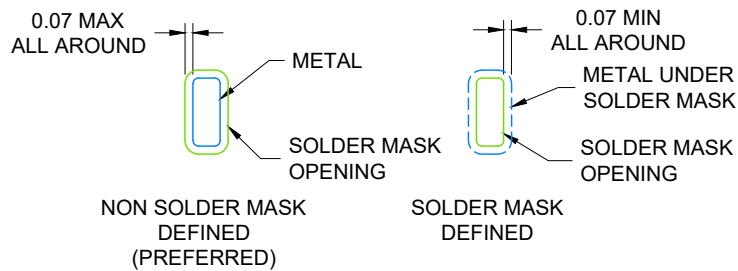


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for optimal thermal and mechanical performance.



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 15X



SOLDER MASK DETAILS

4224734/A 12/2018

NOTES: (continued)

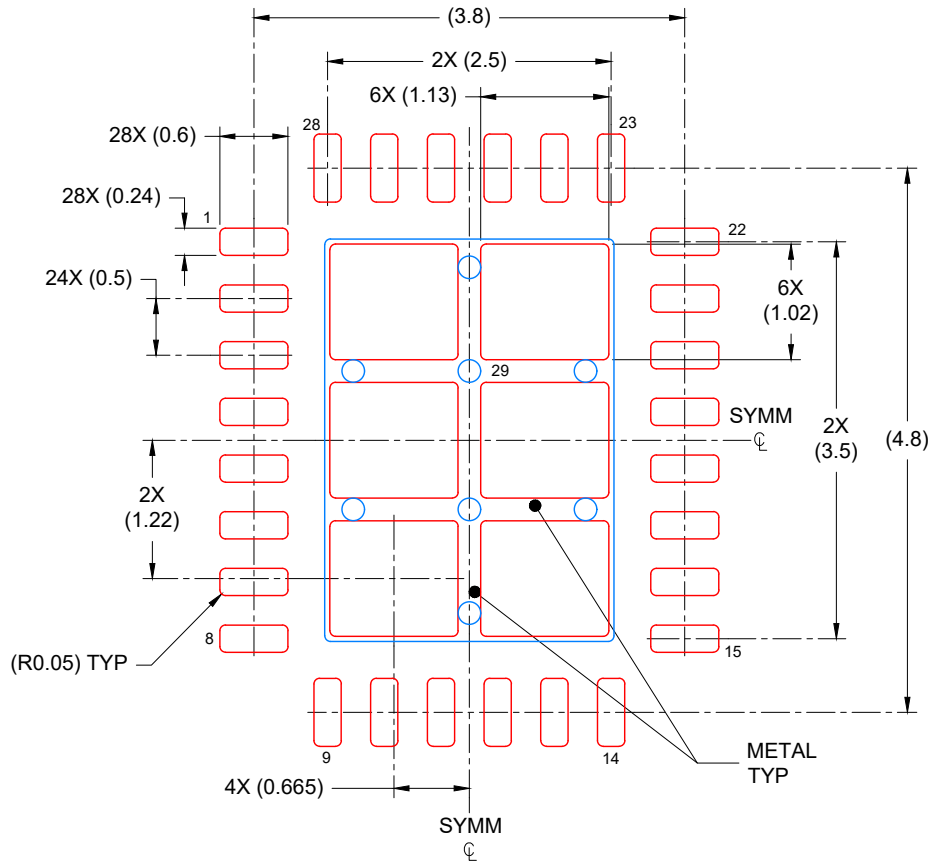
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

# EXAMPLE STENCIL DESIGN

RLH0028A

WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK- NO LEAD



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD  
76% PRINTED COVERAGE BY AREA  
SCALE: 15X

4224734/A 12/2018

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

## 重要なお知らせと免責事項

TI は、技術データと信頼性データ(データシートを含みます)、設計リソース(リファレンス デザインを含みます)、アプリケーションや設計に関する各種アドバイス、Web ツール、安全性情報、その他のリソースを、欠陥が存在する可能性のある「現状のまま」提供しており、商品性および特定目的に対する適合性の黙示保証、第三者の知的財産権の非侵害保証を含むいかなる保証も、明示的または黙示的にかかわらず拒否します。

これらのリソースは、TI 製品を使用する設計の経験を積んだ開発者への提供を意図したものです。(1) お客様のアプリケーションに適した TI 製品の選定、(2) お客様のアプリケーションの設計、検証、試験、(3) お客様のアプリケーションに該当する各種規格や、その他のあらゆる安全性、セキュリティ、規制、または他の要件への確実な適合に関する責任を、お客様のみが単独で負うものとし、

上記の各種リソースは、予告なく変更される可能性があります。これらのリソースは、リソースで説明されている TI 製品を使用するアプリケーションの開発の目的でのみ、TI はその使用をお客様に許諾します。これらのリソースに関して、他の目的で複製することや掲載することは禁止されています。TI や第三者の知的財産権のライセンスが付与されている訳ではありません。お客様は、これらのリソースを自身で使用した結果発生するあらゆる申し立て、損害、費用、損失、責任について、TI およびその代理人を完全に補償するものとし、TI は一切の責任を拒否します。

TI の製品は、[TI の販売条件](#)、[TI の総合的な品質ガイドライン](#)、[ti.com](#) または TI 製品などに関連して提供される他の適用条件に従い提供されます。TI がこれらのリソースを提供することは、適用される TI の保証または他の保証の放棄の拡大や変更を意味するものではありません。TI がカスタム、またはカスタマー仕様として明示的に指定していない限り、TI の製品は標準的なカタログに掲載される汎用機器です。

お客様がいかなる追加条項または代替条項を提案する場合も、TI はそれらに異議を唱え、拒否します。

Copyright © 2025, Texas Instruments Incorporated

最終更新日：2025 年 10 月